

# Scalable Printing of Nanoscale Electronics and Sensors

나노 스케일 전자 및 센서의 확장 가능한 인쇄

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[www.nano.neu.edu](http://www.nano.neu.edu)

[www.nanomanufacturing.us](http://www.nanomanufacturing.us)



Northeastern University



Center for High-rate  
Nanomanufacturing

# Motivation: Cost

## Financial and Environmental Cost

Commercial electronics device manufacturing is still expensive, with fabs costing up to 15 billions and requiring massive quantities of water and power.



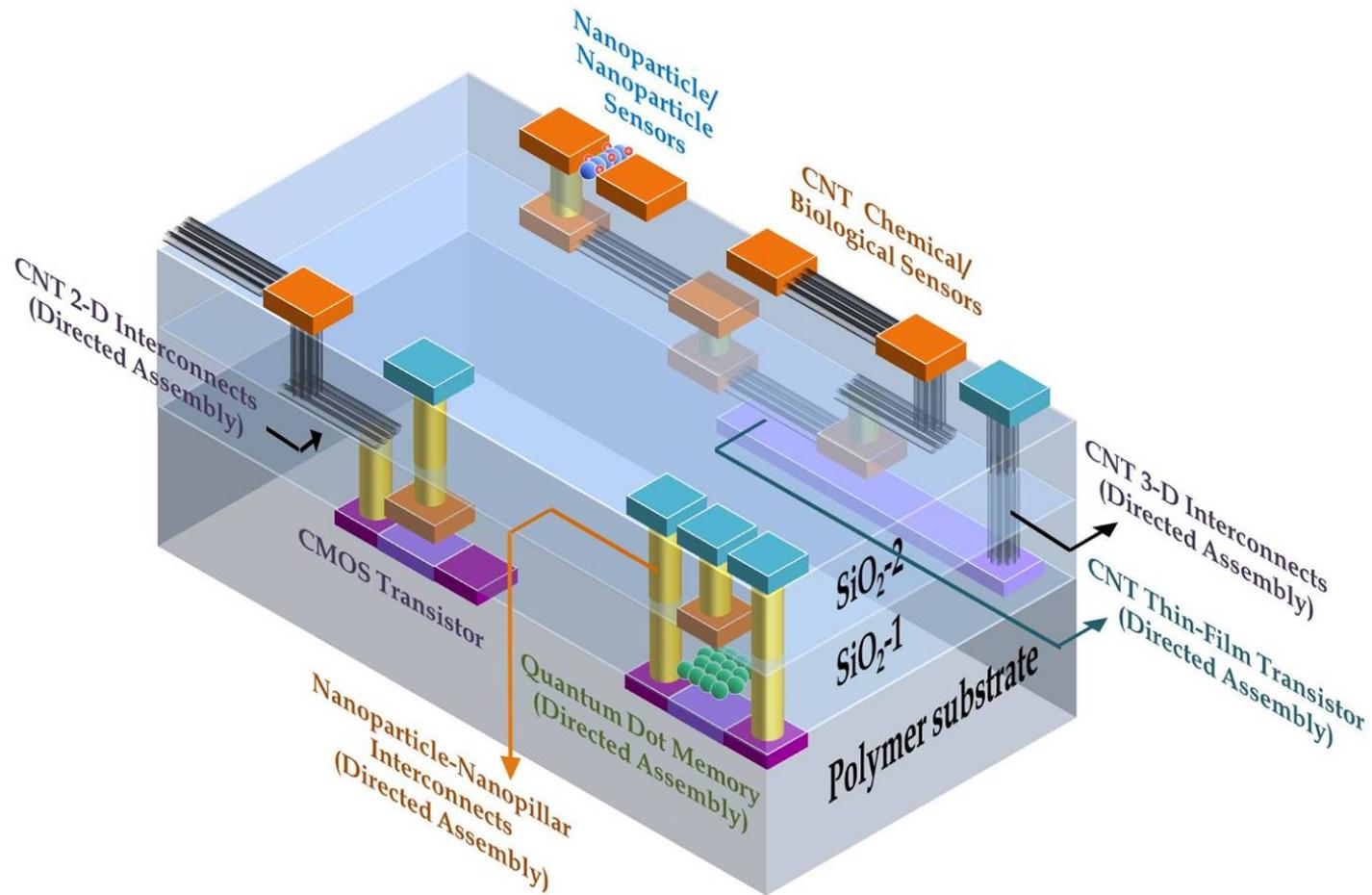
**1990s - \$1B-\$2B**



**2016 - \$17B**

# Motivation: Versatility

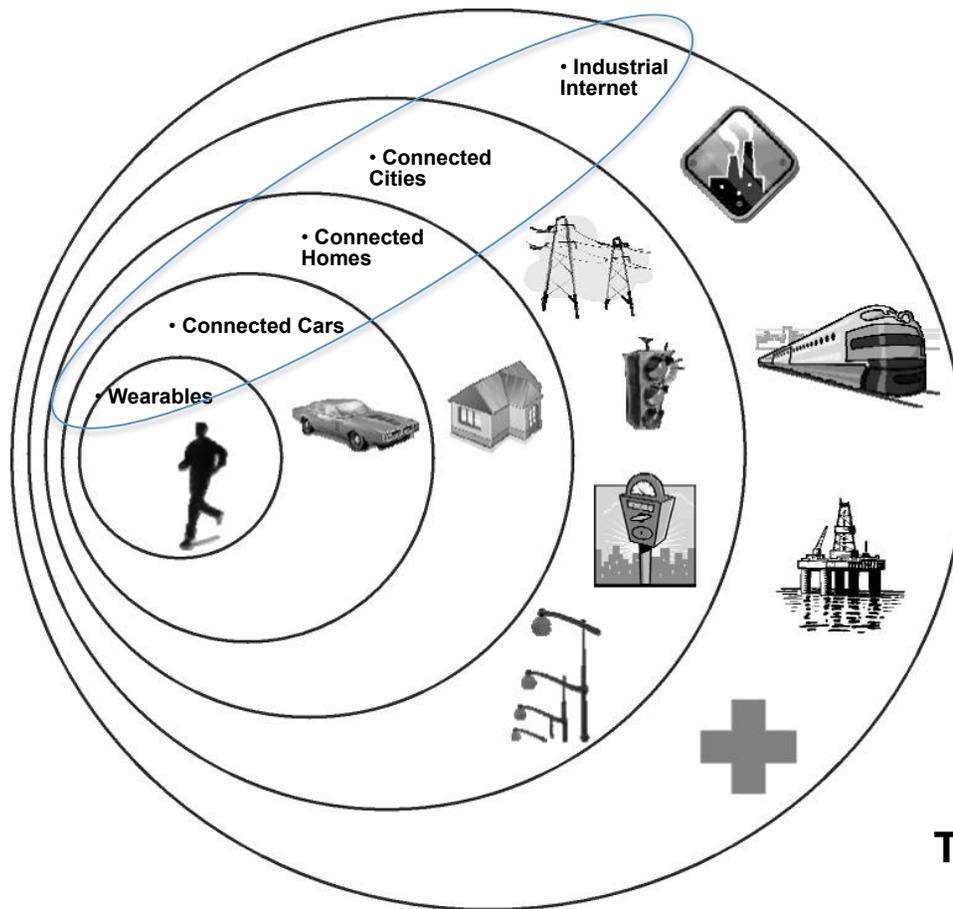
## Can we print any material on any substrate?



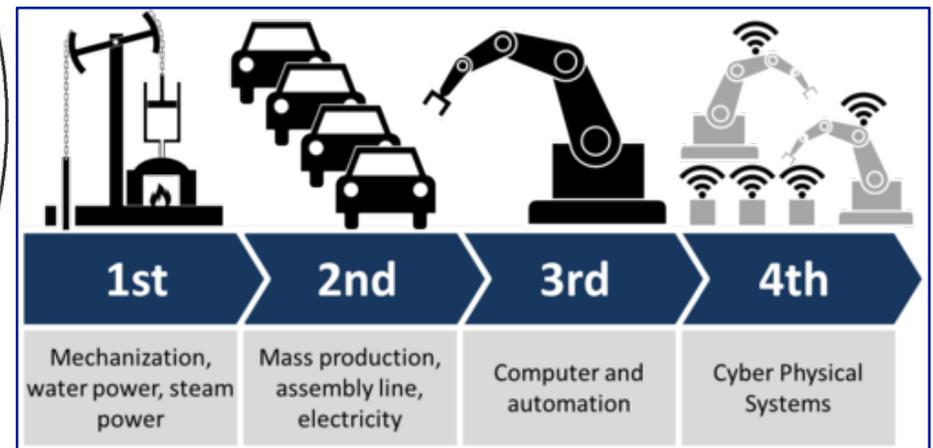
- |                           |                                      |                      |
|---------------------------|--------------------------------------|----------------------|
| Polymer substrate         | Passivation Layer - SiO <sub>2</sub> | Metal Electrodes     |
| Bond Pads                 | Nanoparticle-Nanopillars             | N <sup>-</sup> doped |
| P <sup>+++</sup> doped    | CNT Interconnects                    | Quantum Dot          |
| Nanoparticle/Nanoparticle |                                      |                      |

# Motivation: IoT Opportunities

IoT has five key verticals: **Wearable Devices, Cars, Homes, Cities, and the Industrial Internet**. Impact by 2025 is \$3.9-\$11.1 Trillions.



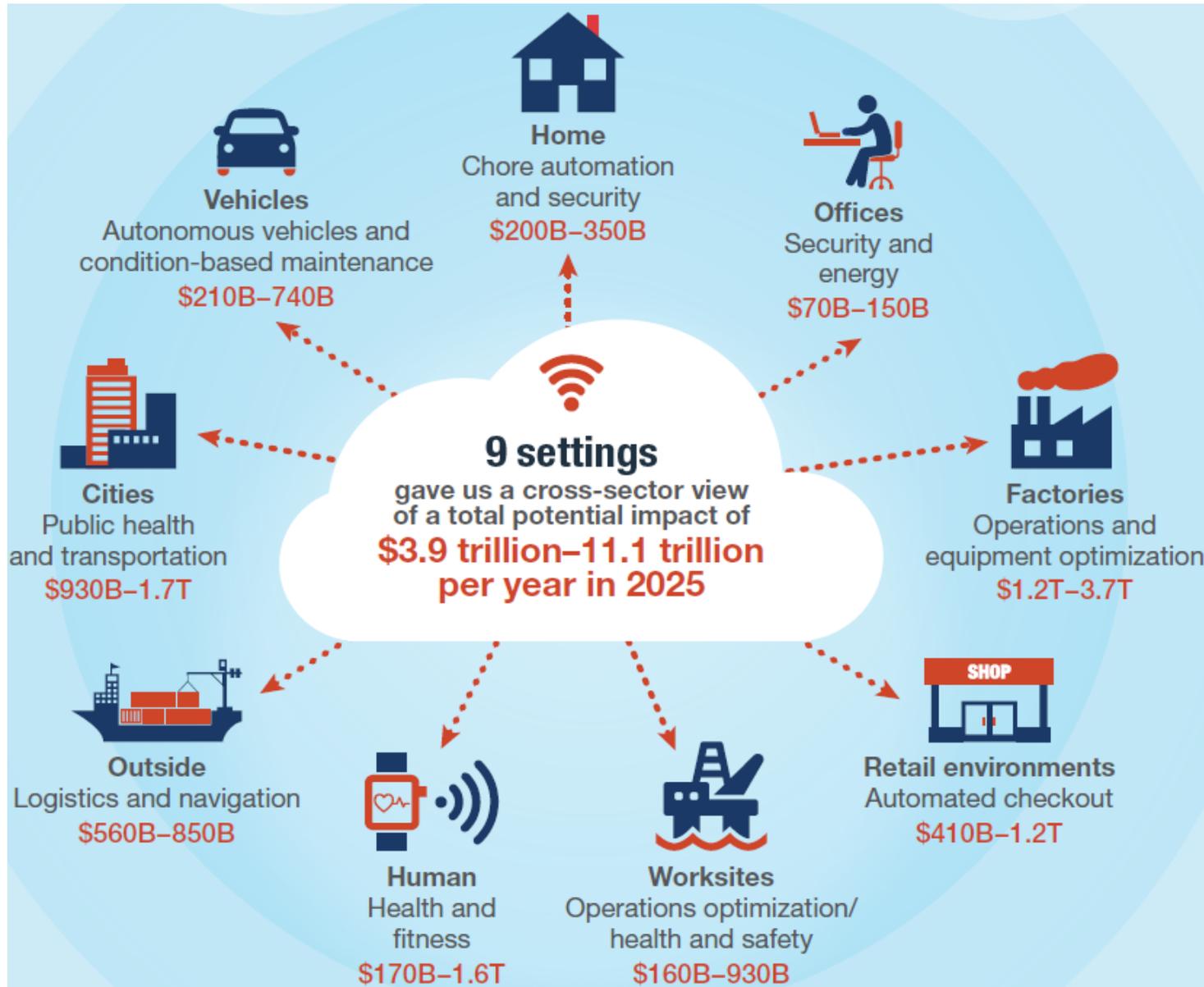
The IoT can only be enabled by breakthroughs in the cost of **ubiquitous sensors** for collecting and sharing data



**The four industrial revolutions & Industry 4.0;  
Industrial Internet**

# The IoT Nine Applications

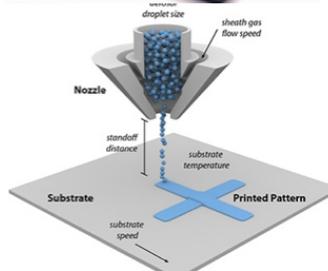
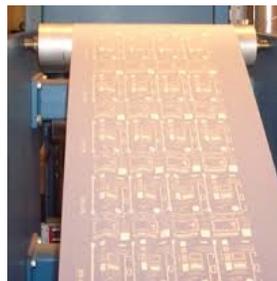
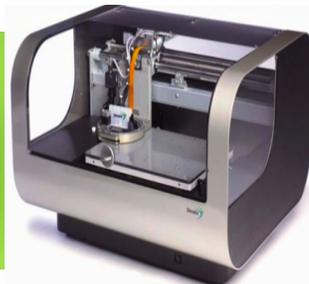
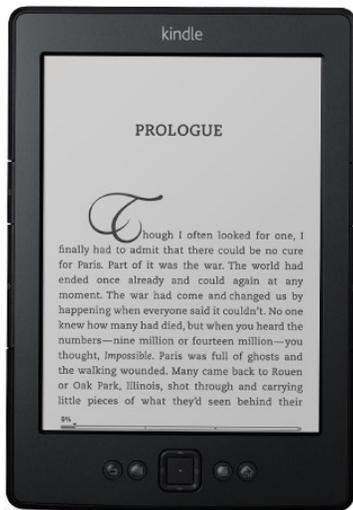
Nine key areas where IoT is expected bring up to \$11Trillion in 2025.



McKinsey  
Global  
Institute,  
2016.

# State of the Art - Printing Technologies

- Current electronics and 3D printing using inkjet technology, used for printing low-end electronics but **can only print down to 20 microns (20,000 nanometers)**.
- 20 microns was the silicon electronics line width in 1975.
- Cost of a currently printed electronics is 10 to 100 times less than the cost of current silicon-based sensors.



- A printing technology is needed that can **print conductive, semiconducting, and insulating materials (inorganic or organic) down to 20nm and 1000 times faster than inkjet.**
- There is need to print Inter-connected multilayers.

# How can electronic printing leap from 1975 to Today?

The NSF Center for High-rate Nanomanufacturing has developed the technology to print electronics with 20 nm minimum line width or smaller.

## However, is nanoscale printing alone enough?

- For printed electronics and devices to compete with current silicon-based nano and microscale electronics, it has to print nanoscale features at:
  - orders of magnitudes faster than inkjet based printers and
  - cost should be fraction of the current cost for making silicon-based electronics

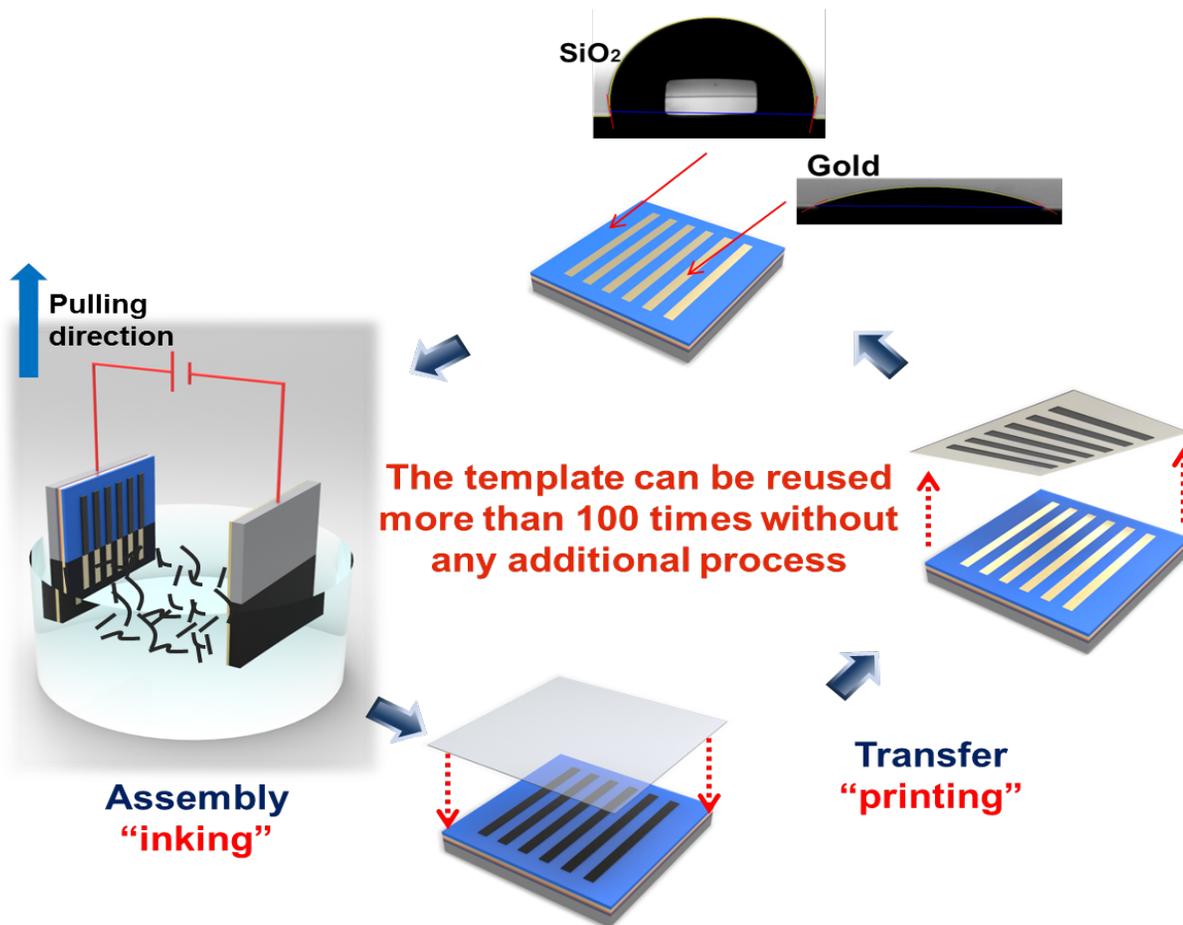


# CHN Directed Assembly Toolbox

Process	Speed	Scalability	Nanoelement property	Mechanism	Demonstrated assembly of
Convective	Slow	No	Surface Functionalization	Convection	Nanoparticles
Convective interfacial	Fast	Yes	Surface functionalization and surface tension	Convection and interfacial force	Nanoparticles, 2D materials
Chemical functionalization/ fluidic	Fast/ slow	Yes	Functionalization	Chemistry	Nanoparticles, CNTs, polymers, 2D materials
Electrophoretic and chemical functionalization (NanoOPS)	Fast	Yes	Charge and surface functionalization	Electrophoresis and surface energy	Nanoparticles, CNTs, polymers, 2D materials
Electrophoretic Assembly on Conductors or Insulators	Fast	Yes	Charge	Electrophoresis	Nanoparticles, CNTs, polymers, 2D materials
Dielectrophoretic	Fast	Yes/No	Dielectric constant	Dielectrophoresis	Nanoparticles, CNTs, 2D materials, polymers,

# How does it work?

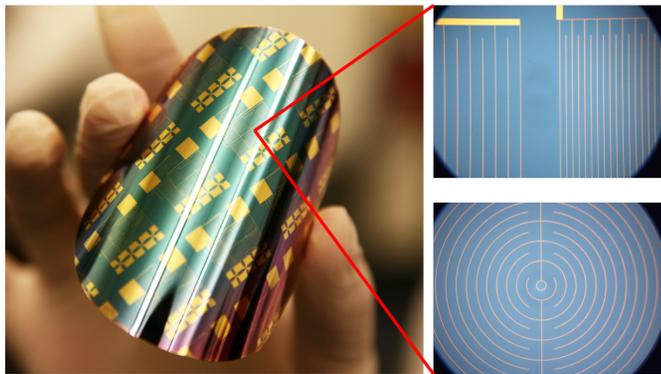
# Beyond 3-D & Electronic Printing: Nanoscale Offset Printing Advantages



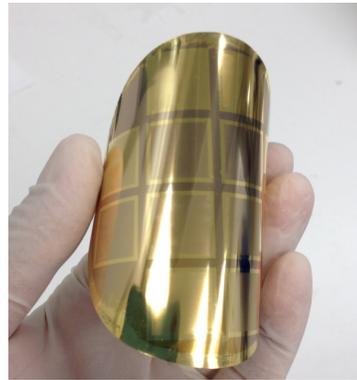
- Additive
- High throughput
- Prints down to 20nm
- Room temperature and pressure
- Prints on flexible or hard substrates
- Multi-scale; nano to macro
- Material independent
- Very low energy consumption
- Very low capital investment

*Advanced Materials, 2015, 27, pp. 1759–1766.*

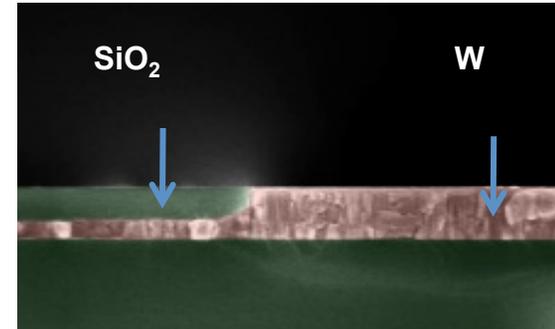
# Damascene Templates for Nanoscale Offset Printing



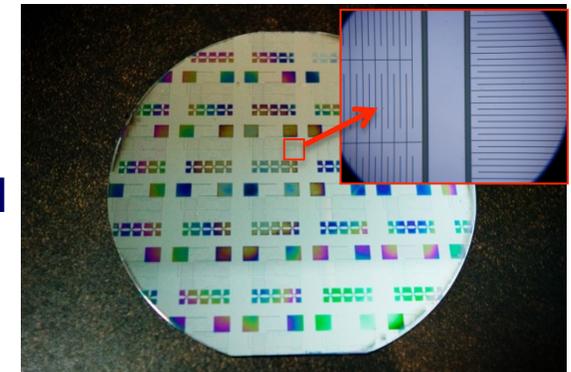
**PEN**  
**Polymer-based  
Templates**



**PI**

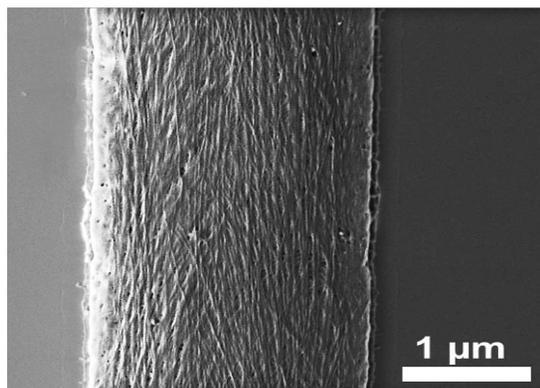


**Silicon-  
based Hard  
Templates**

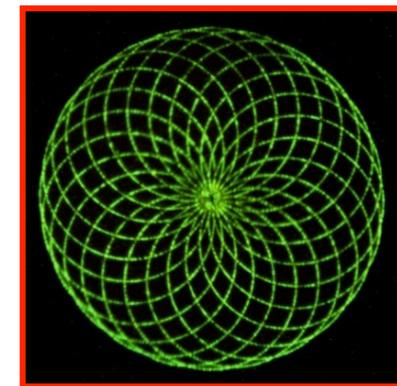
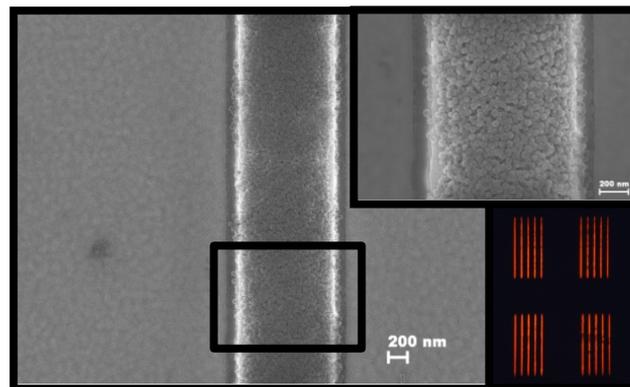


*Advanced Materials, 2015*

**Assembled SWNT**

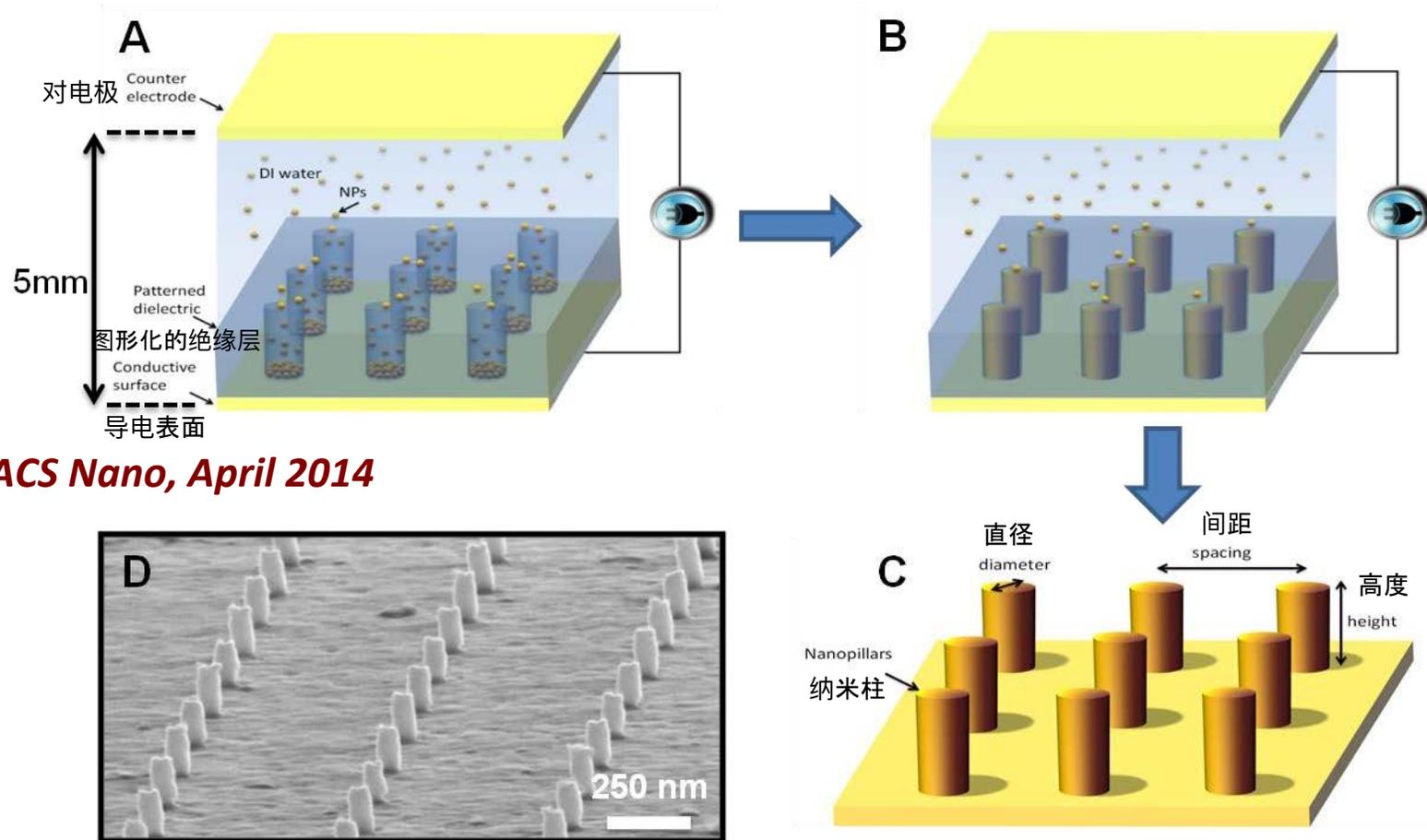


**Assembled Particles**





# Directed Assembly-based Printing of Interconnects 用于互连的定向自组装



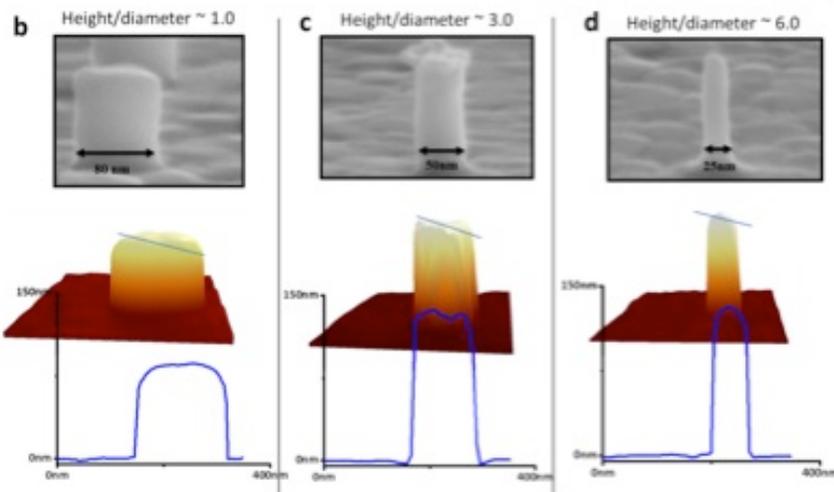
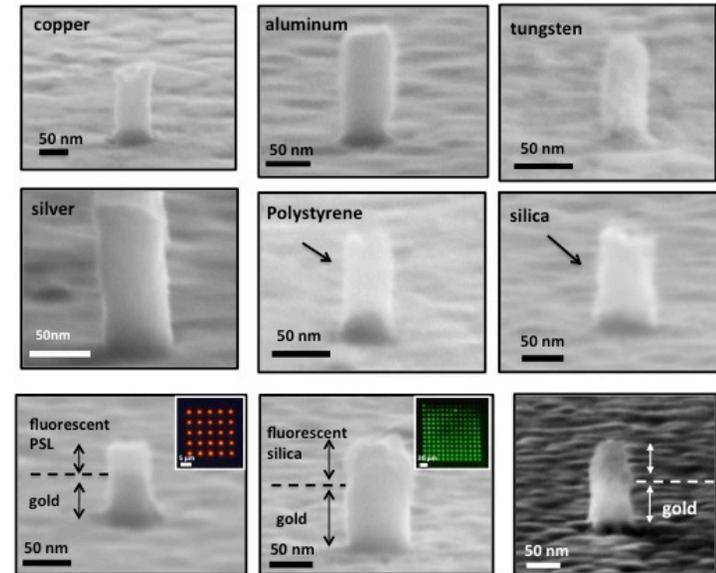
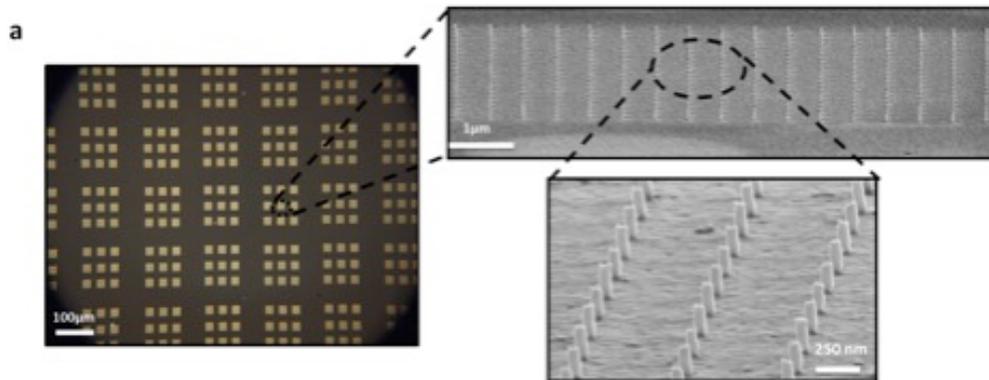
*ACS Nano, April 2014*

•Manufacturing of 3-D nanostructures using directed nanoparticle assembly process. (A and B) NPs suspended in aqueous solution are (A) assembled and (B) fused in the patterned via geometries under an applied AC electric field. (C) Removal of the patterned insulator film after the assembly process produces arrays of 3-D nanostructures on the surface. (D) Scanning electron microscopy (SEM) image of gold nanopillar arrays. 使用纳米颗粒定向自组装工艺制造3D纳米结构。(A和B) 水溶液中的纳米颗粒在交流电场的作用下被组装 (A) 到孔形的结构中, 并熔化 (B) 形成纳米柱。(C) 组装结束后, 去除用于形成孔形结构的绝缘薄膜就会出现成列的3D纳米结构。(D) 金纳米柱阵列的扫描电镜图片。

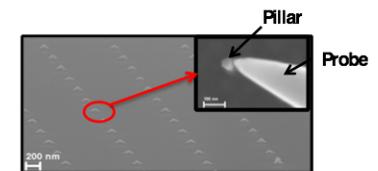
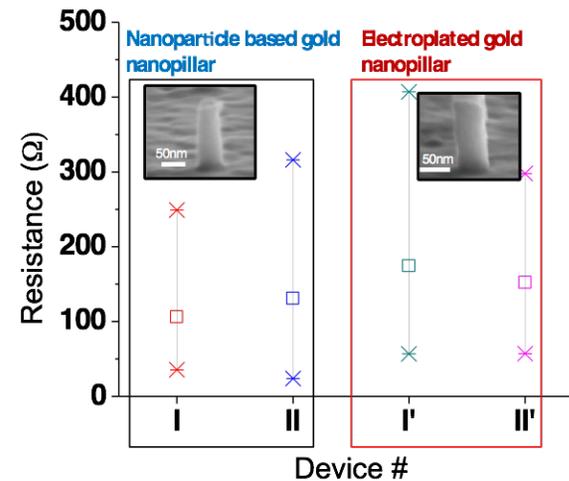


# Fabrication of Interconnects with Controlled dimensions

## 尺寸可控的互连结构制造

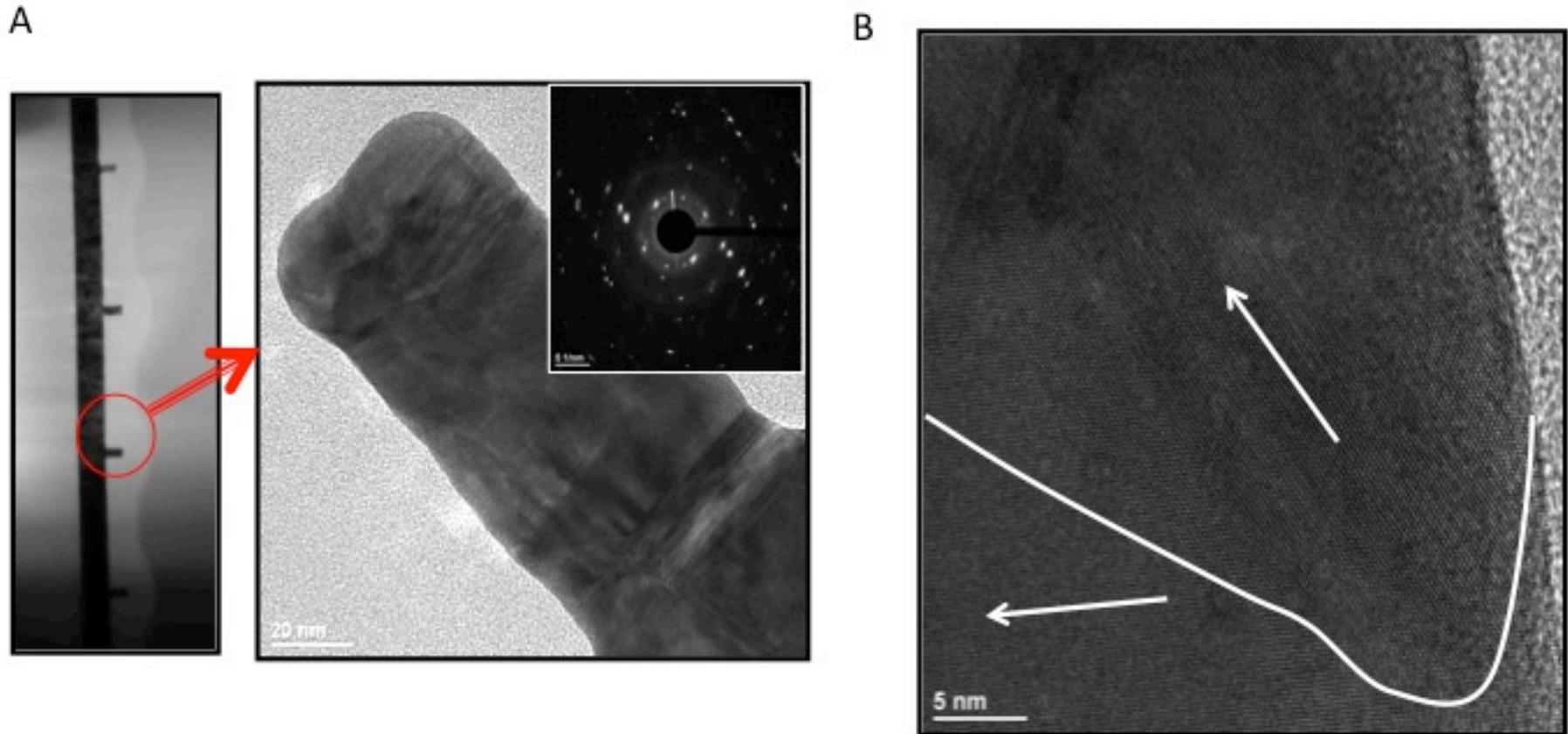


*Cihan Yilmaz et al., ACS Nano, 2014, 8 (5), pp 4547–4558*



- Fabrication over a large area.
- Controlled, repeatable and reliable fabrication.

# Do particles completely fuse following the assembly?



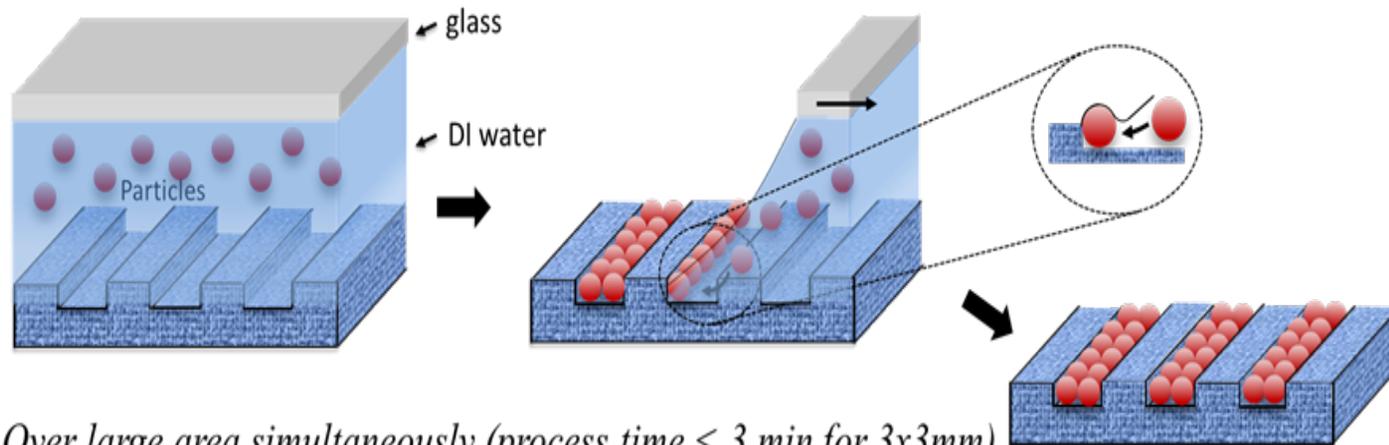
- TEM shows that NPs completely fuse without any voids or gaps.
- Nanopillars have polycrystalline nature.

# Mechanism of Interfacial Convective Assembly Results

## Convective vs interfacial convective assembly

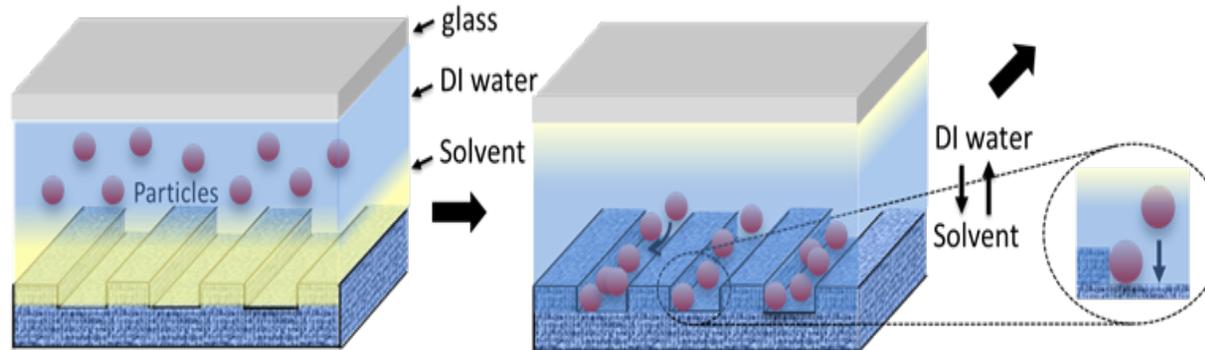
**a** Only in the interface region (process time > 2 hours for 3x3mm)

*Nature Nano 2007*



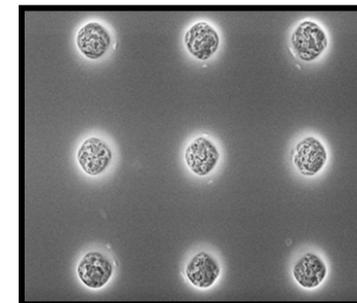
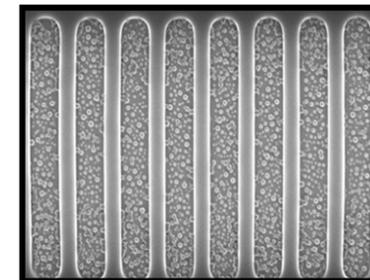
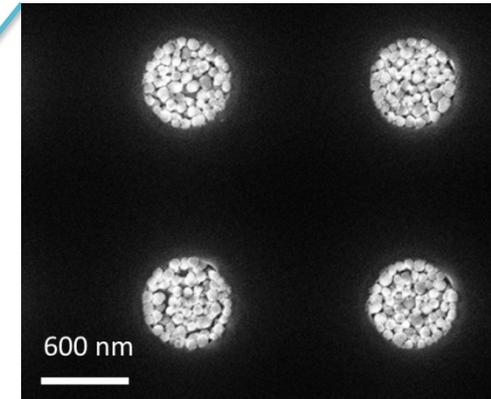
**b** Over large area simultaneously (process time < 3 min for 3x3mm)

*Our Process*



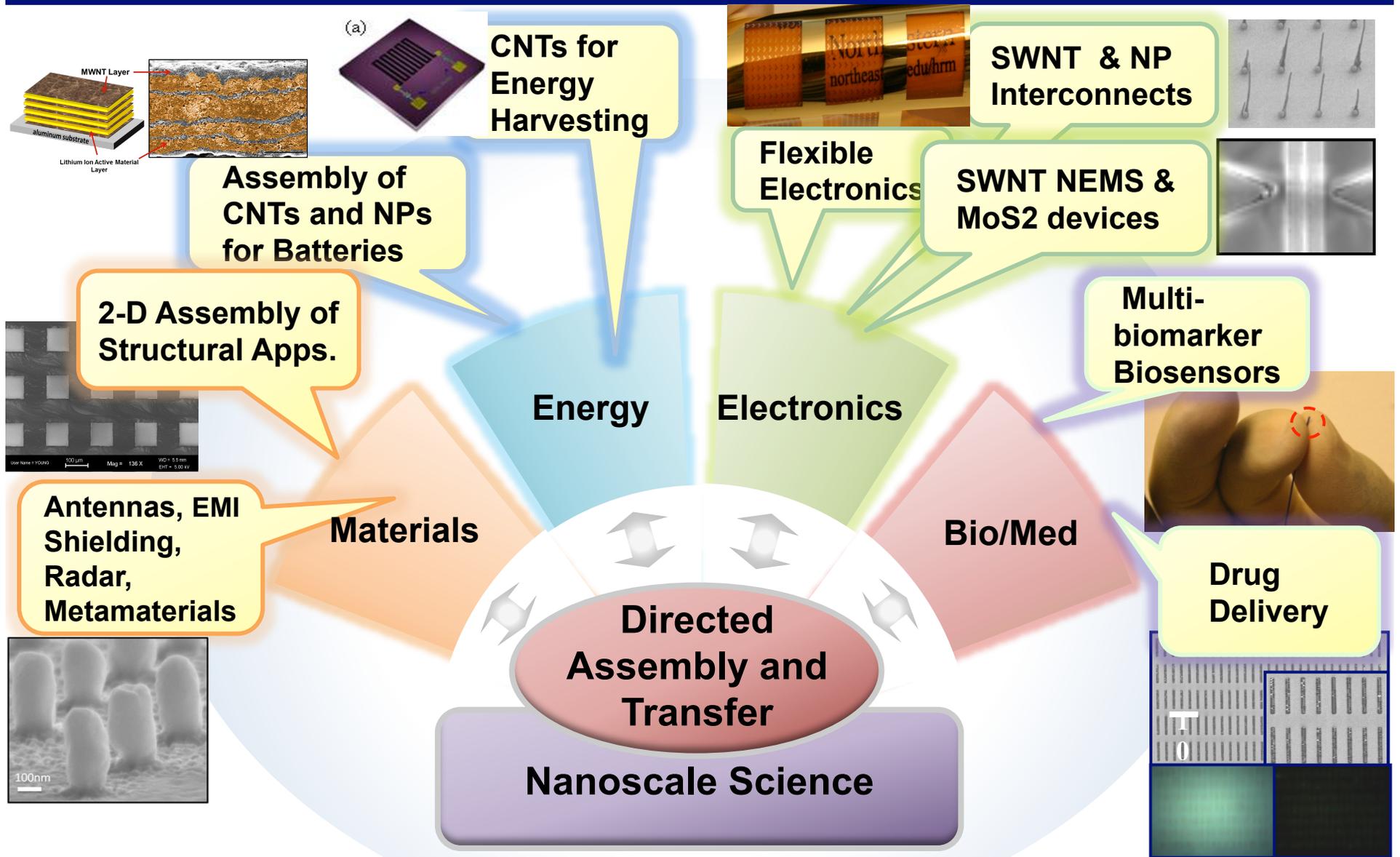
# Assembly of NPs into Trench and Vias Over Large Areas

***Particle: 30nm fluorescent (green) silica NPs***  
***Assembly time: <10 min***



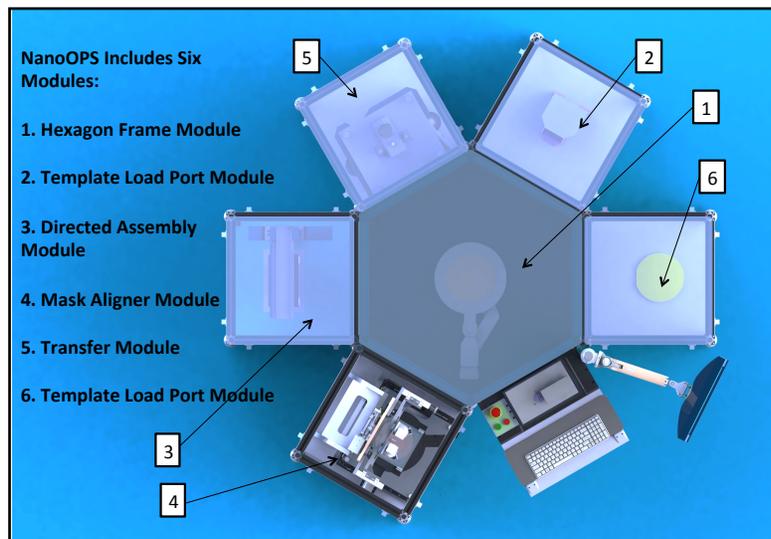
**No electrophoretic or Di electrophoretic force is used.**

# What Could We manufacture with Multiscale Offset Printing?



# The world's first Printer NanoOPS (Nanoscale Offset Printing System)

- Capable of printing down to 20nm, 1000 times faster than inkjet and costs 10 to 100 times less than conventional nanofabrication.
- Fully automated and integrated registration and alignment.

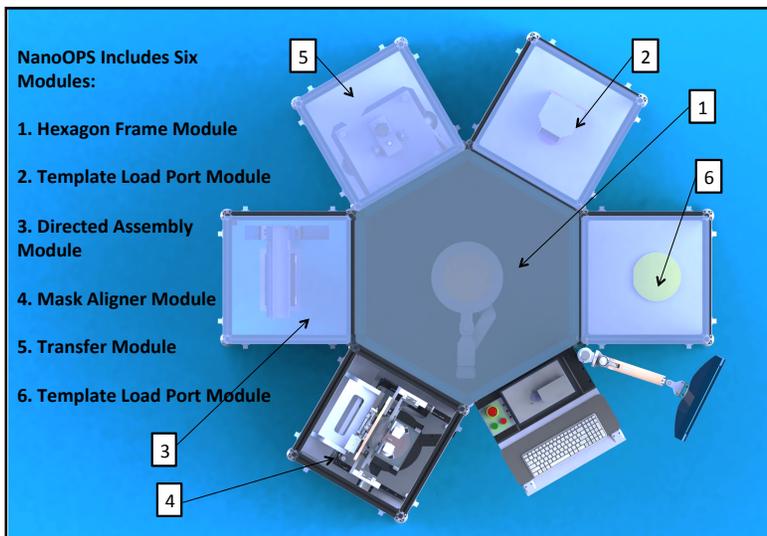


**Present:** Microelectronics Factory: \$10B-\$15B >>>>  
**Future:** Nanomanufacturing Factory: \$50-\$100M



# Fully Automated Nanoscale Offset Printing System (NanoOPS) Prototype was Demonstrated to more than 58 companies

- NanoOPS is capable of printing using templates with micro and nanoscale patterns (down to 20nm).
- Integrated registration and alignment.



NanoOPS Videos on Youtube:

From Lab to Fab: Pioneers in Nano-Manufacturing

<https://www.youtube.com/watch?v=tZeO9I1KEec>

NanoOPS at Northeastern University

<https://www.youtube.com/watch?v=2iEjlcog774>

NanoOPS - A Nanomanufacturing Breakthrough

<https://www.youtube.com/watch?v=J4XupF3Zt5U>



# The World's First Nanoscale Printer for Electronics Awards and Publicity

2016

FLEXI  
AWARD

Printed Electronics Conf., Berlin 2016



Best Academic R&D  
Award

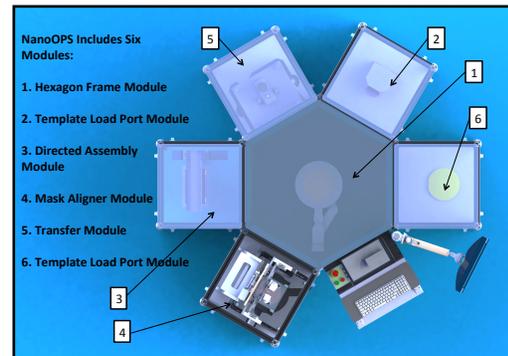
IDTechEx Show! EUROPE 2016



The Boston Globe



The world's first Nanoscale Printing System for electronics and sensors.



1000 times faster printing with a 1000 times smaller features than inkjet or 3D printing.



NanoOPS Videos on Youtube:

From Lab to Fab: Pioneers in Nano-Manufacturing: <https://www.youtube.com/watch?v=tZeO9l1KEec>

NanoOPS at Northeastern University: <https://www.youtube.com/watch?v=2iEjlcog774>

# Strong Industrial Partnerships



Over 30 Companies

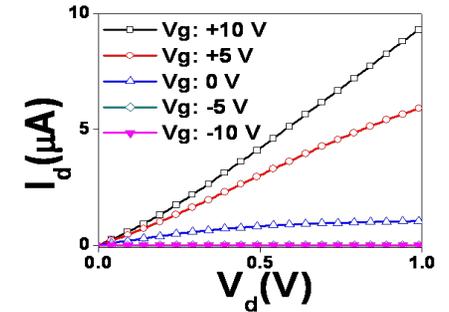
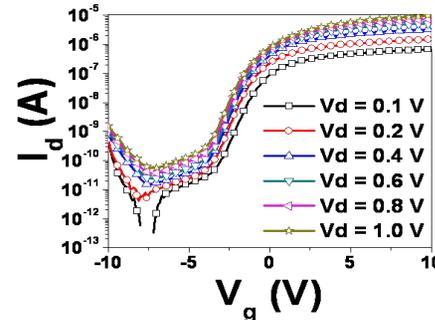
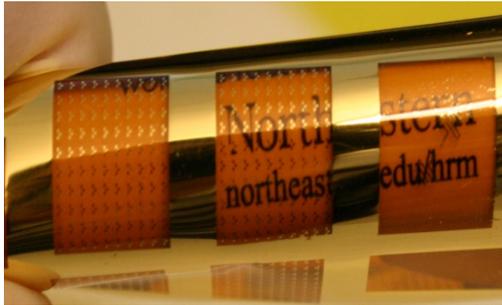
# Applications

## Nanoelectronics

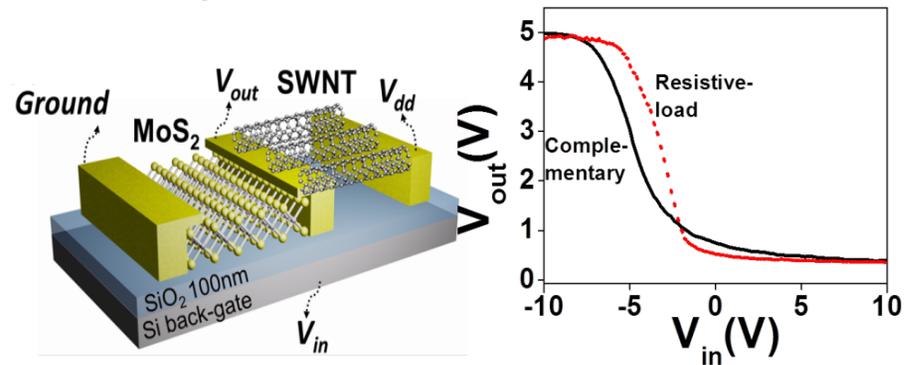
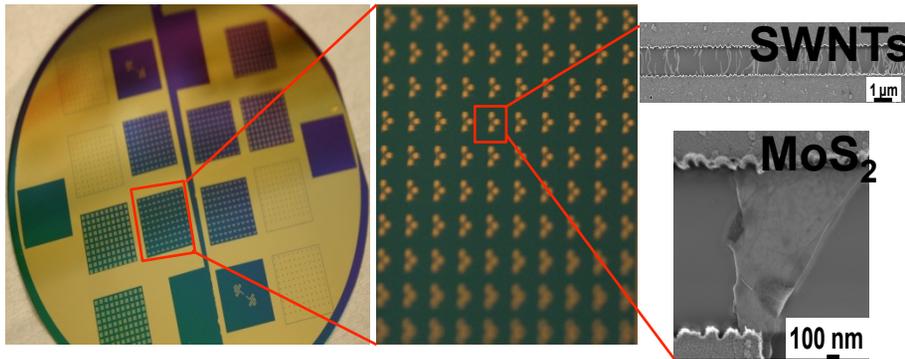
Using 0, 1 and 2 D Nanomaterials, Organic Semiconductors or Inorganic Narrow or Wide-Bandgap Semiconductors.

# Printed Nanomaterials-based Electronics

## ➤ Flexible transparent n-type MoS<sub>2</sub> transistors



## ➤ Heterogeneous SWNTs and MoS<sub>2</sub> complimentary invertors

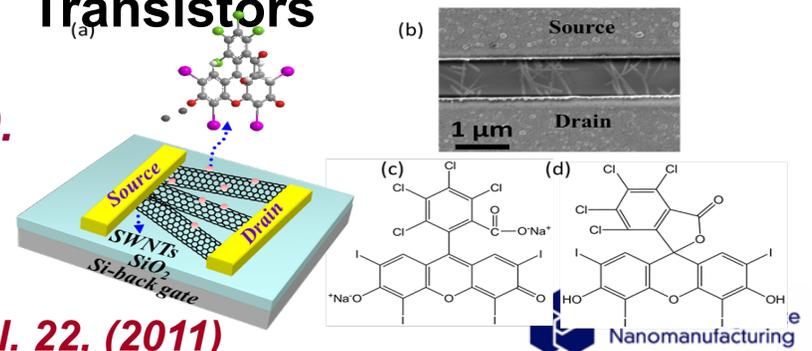


*Nanotechnology, Vol. 23, (2012).*

## ➤ Rose Bengal Molecular Doping of CNT Transistors



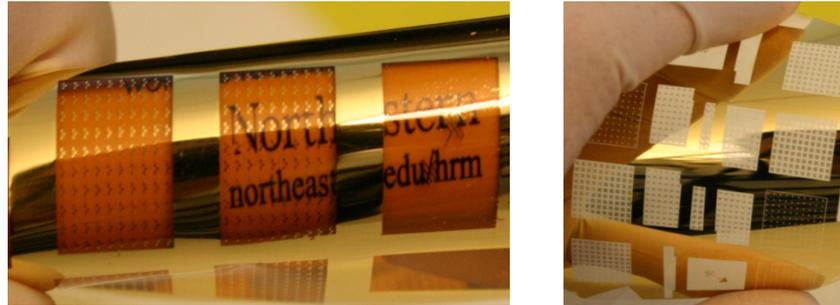
*Appl. Phys. Lett. 97, 1 2010.*



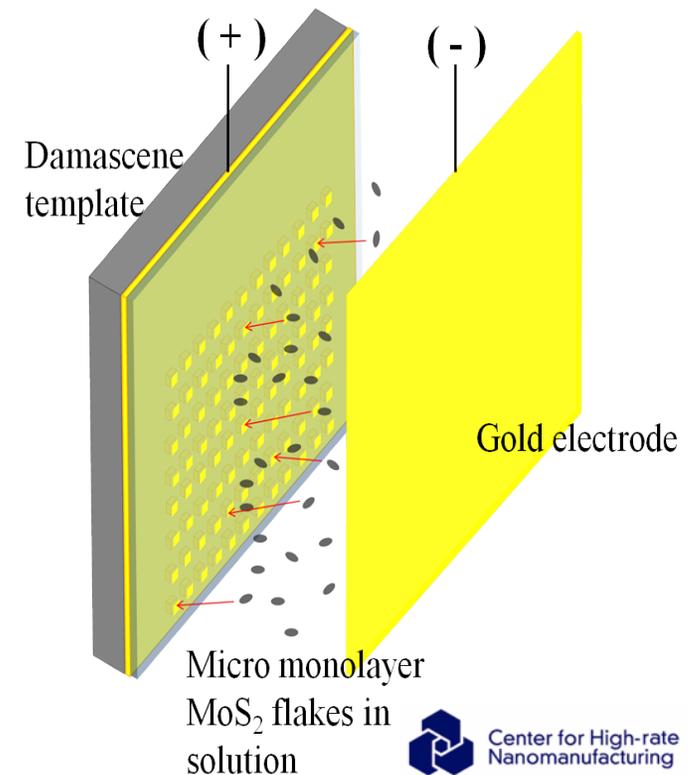
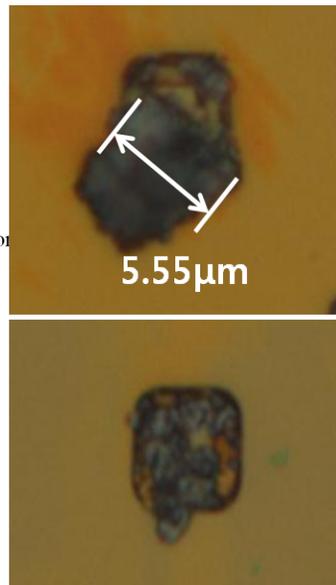
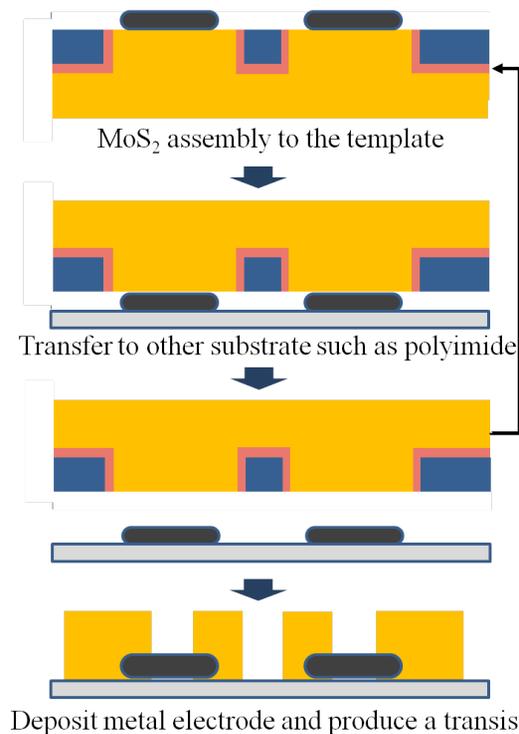
*Nanotechnology, Vol. 22, (2011)*

# Printing Nanomaterials-based Electronics

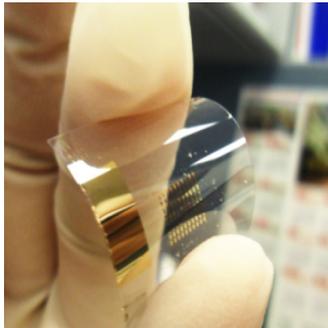
## ➤ Flexible transparent n-type $\text{MoS}_2$ transistors



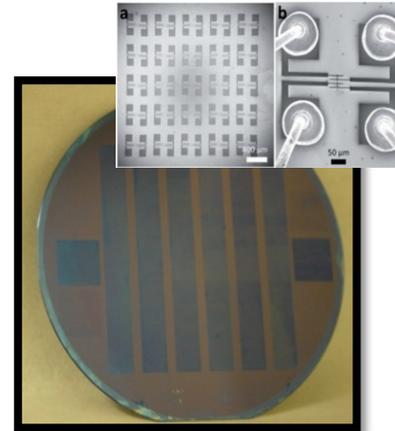
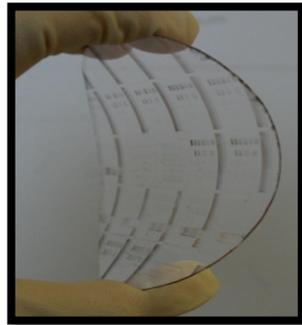
## ➤ Heterogeneous SWNTs and $\text{MoS}_2$ complimentary invertors



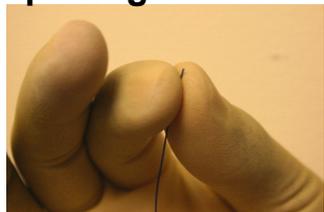
# Printing Wireless Sensors and Electronics at a Fraction of their Current Cost



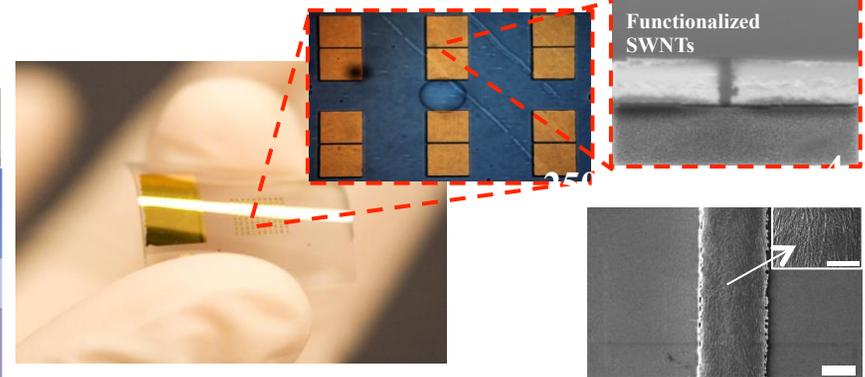
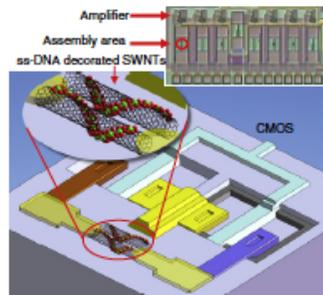
Sensors for E. coli bacteria, viruses, and other pathogens



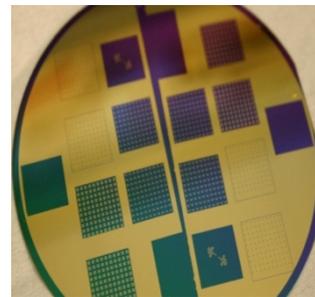
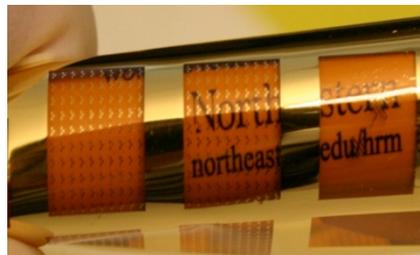
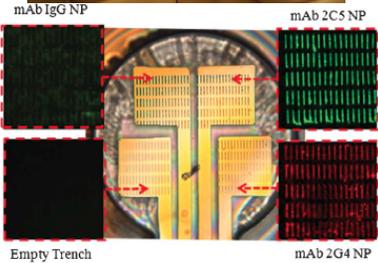
Sensors for Chemicals



Cancer and cardiac diseases. Detection limit is 200 times lower than Current technology



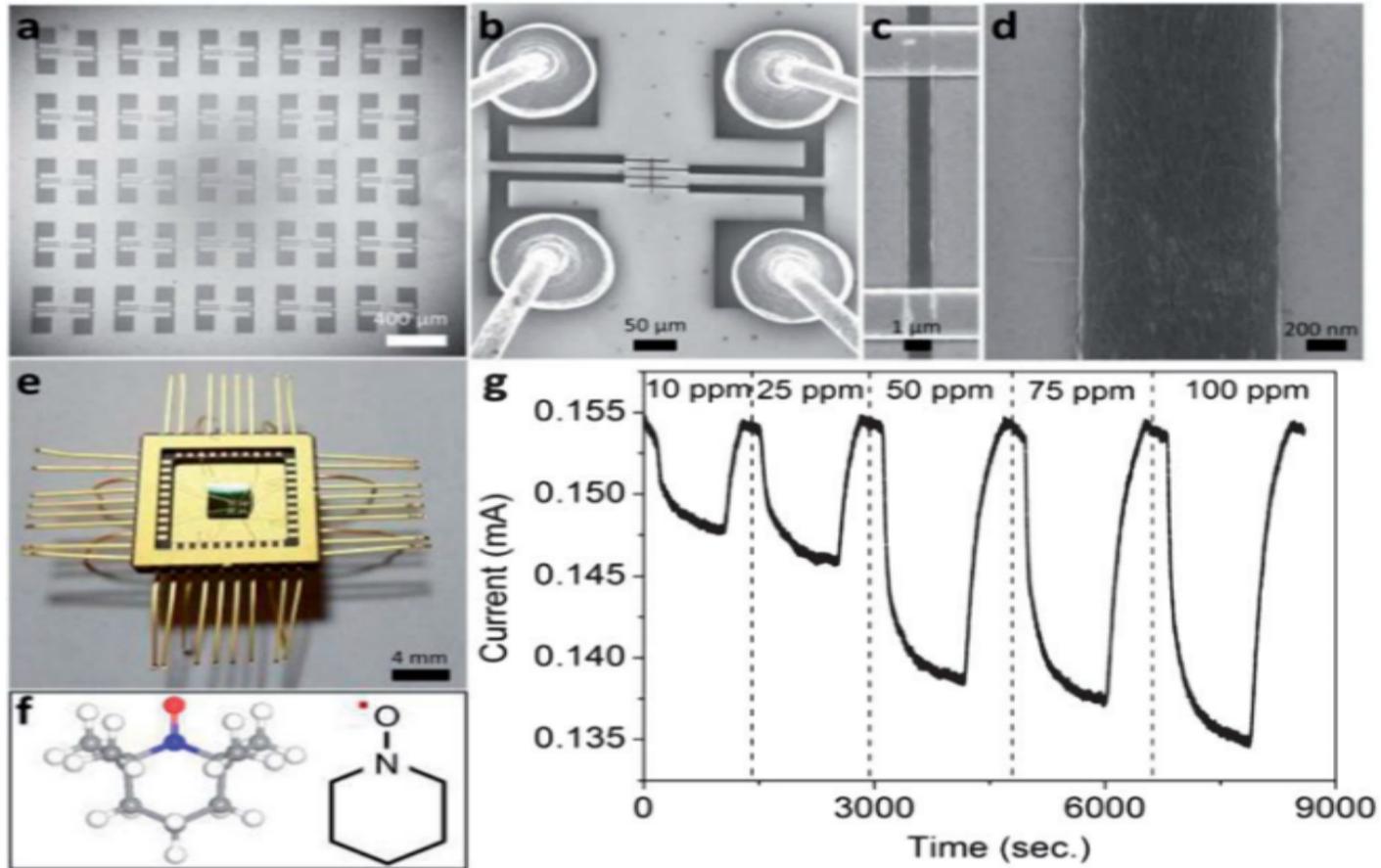
Band-Aid sensor



Supporting printed electronics for sensor systems

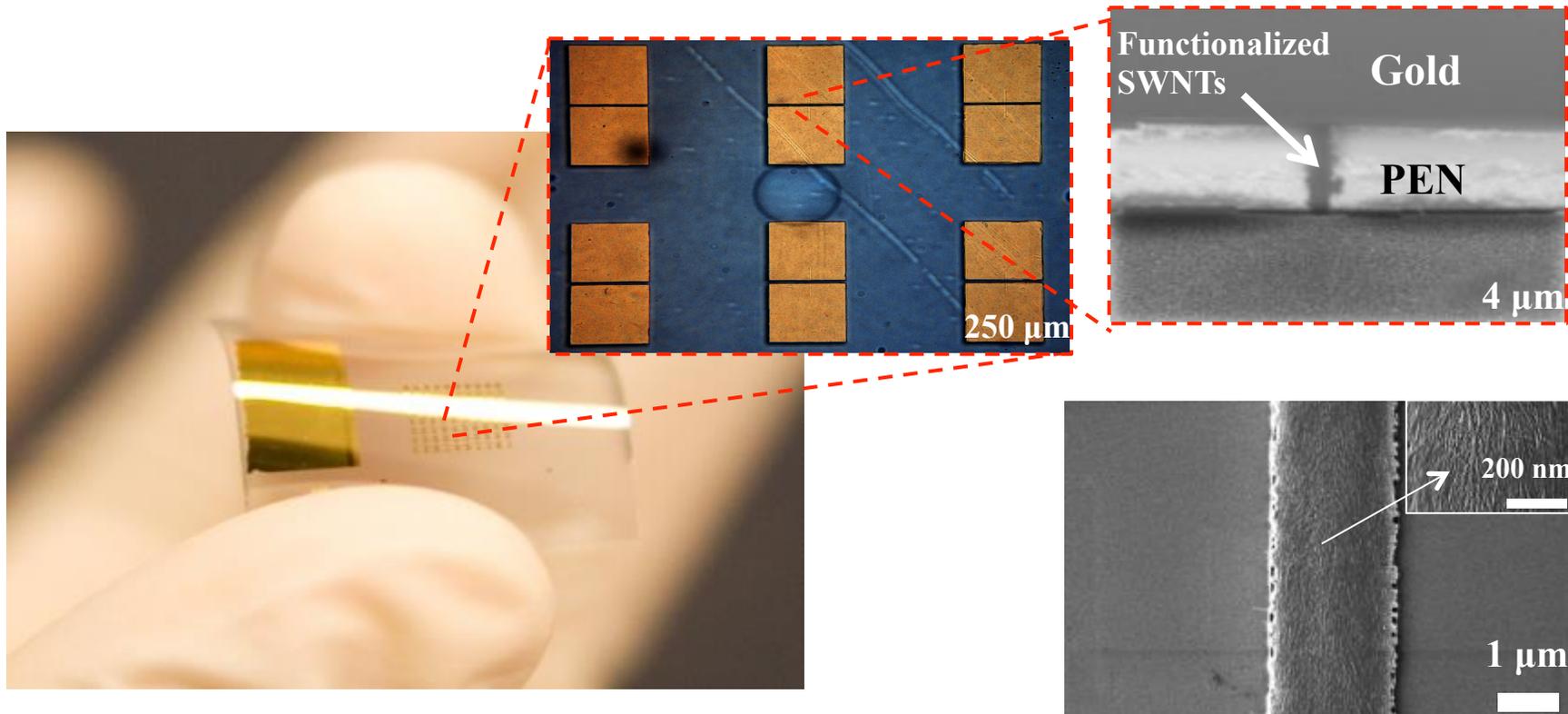


# Printed Chemical Sensors

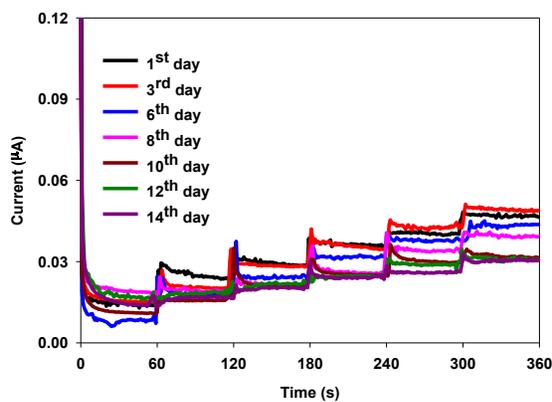
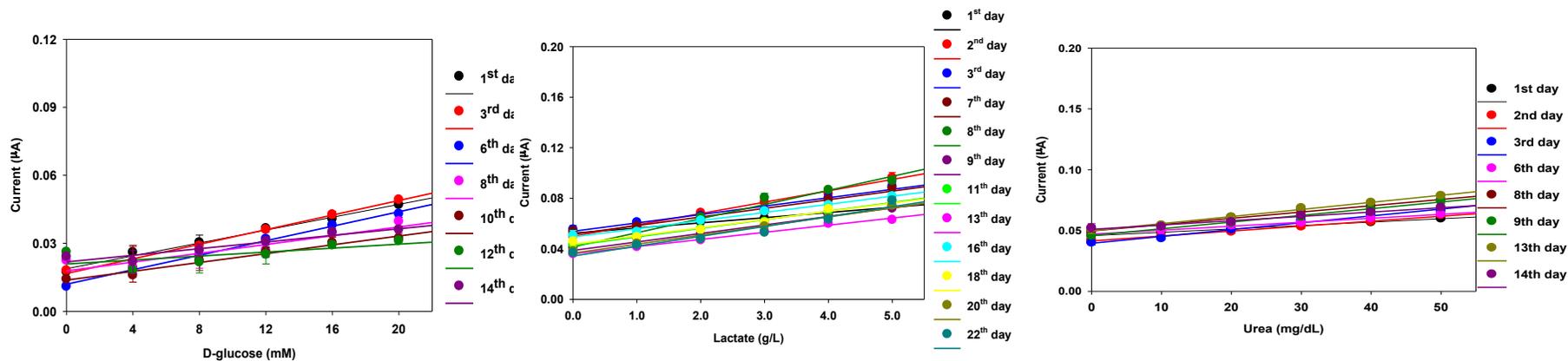


SEM images setup for assembled SWCNT array devices. (e) An optical image of wafer scale sensor devices. (f) Chemical structure of TEMPO molecules. (g) Real-time current changes as a function of conc. H<sub>2</sub>S gas at 10, 25, 50, 75 and 100 ppm for the functionalized SWCNT sensor.

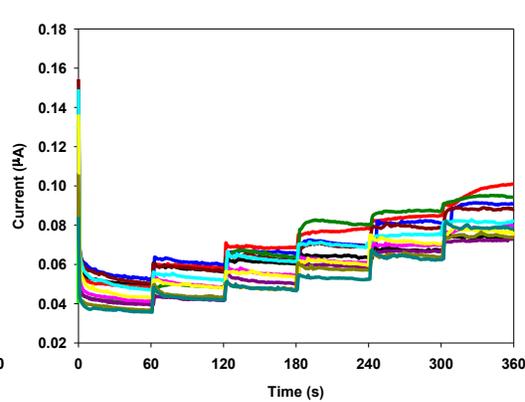
# Flexible CNT Bio Sensors for Glucose, Urea and Lactate in Sweat or Tears



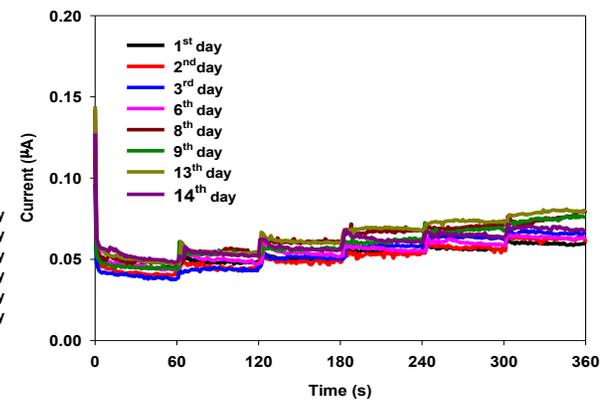
# Stability of D-glucose/L-lactate/urea detections (2~4 weeks)



(A) D-glucose



(B) L-lactate

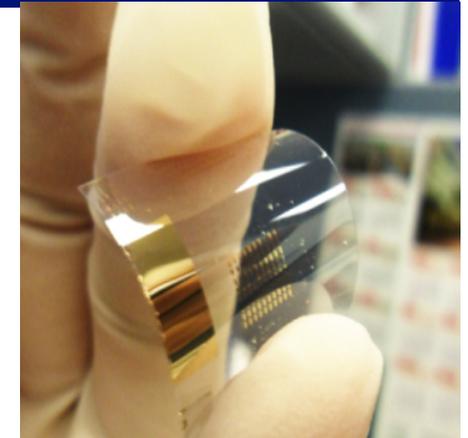
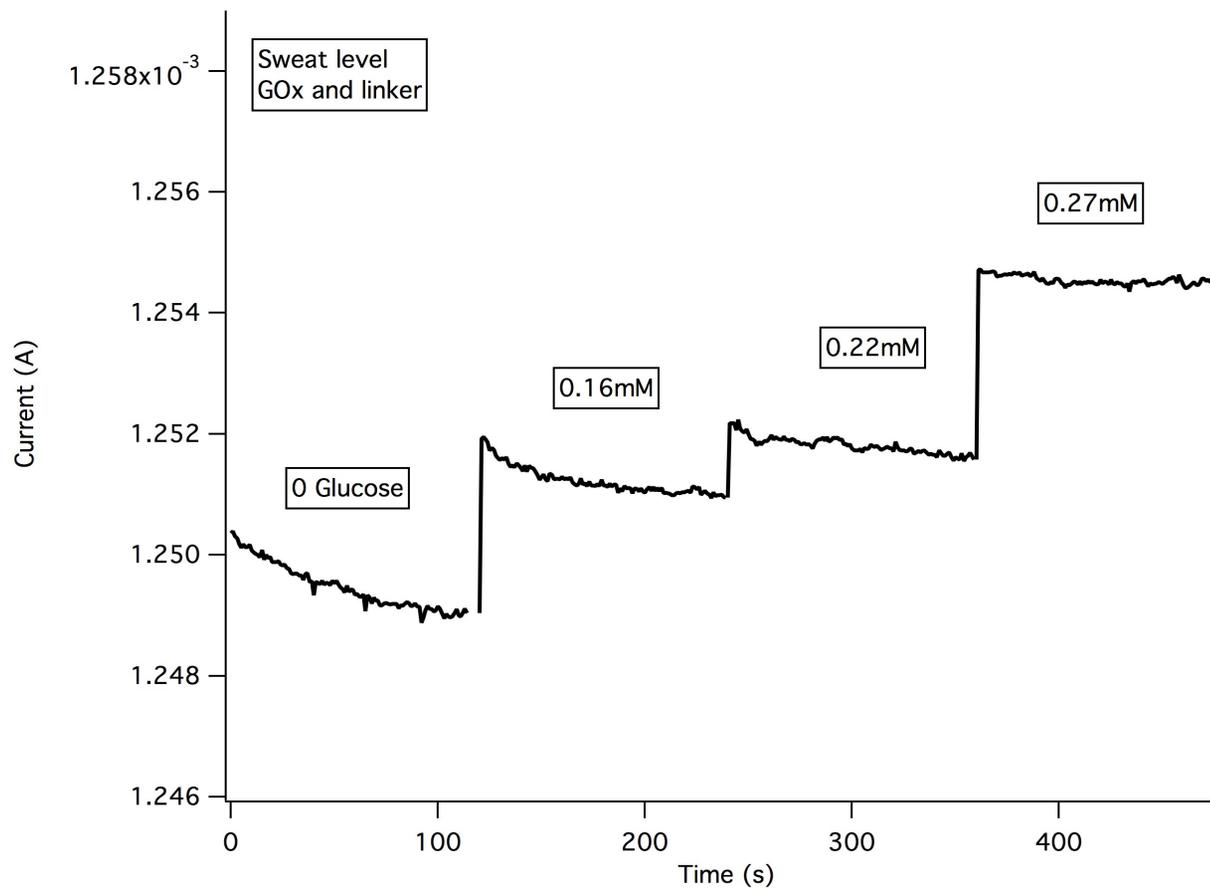


(C) Urea

# Printed Sensor for Glucose Detection in Sweat

## Mediator-free 3<sup>rd</sup> generation sensors

### Glucose detection from Sweat



# How does state of the art compares?

## Commercial Sensors

Weight: 5.5 lbs



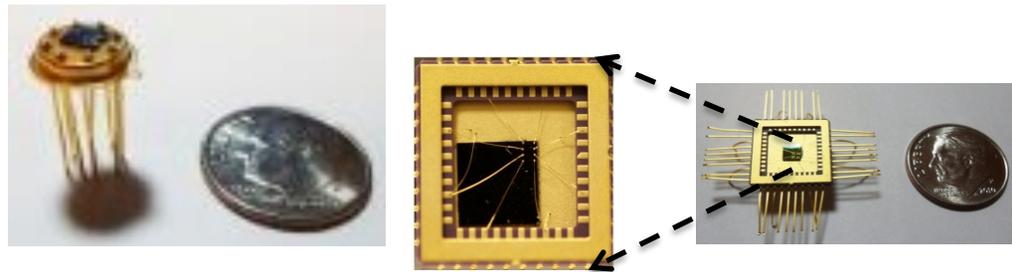
Commercial Chemical Hydrogen Sulfide (H<sub>2</sub>S) Sensors

Weight: 4.15 lbs



## The Sensors developed by the CHN

Weight: 0.000220462 lbs



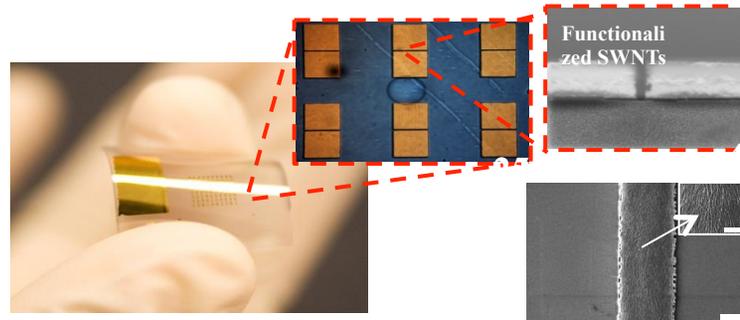
Our Chemical Hydrogen Sulfide (H<sub>2</sub>S) Sensors



Commercial Glucose Sensors use blood



Our "Band-Aid" sensor uses sweat or tears to detect glucose. And can be used to detect viruses, bacteria, cancer, etc.



- Current Sensors are large and consume more energy
- Most sensors are not wearable, flexible or wireless

# A New Spinout to Make the Nanoscale Printing Systems Available to Industry and Researchers

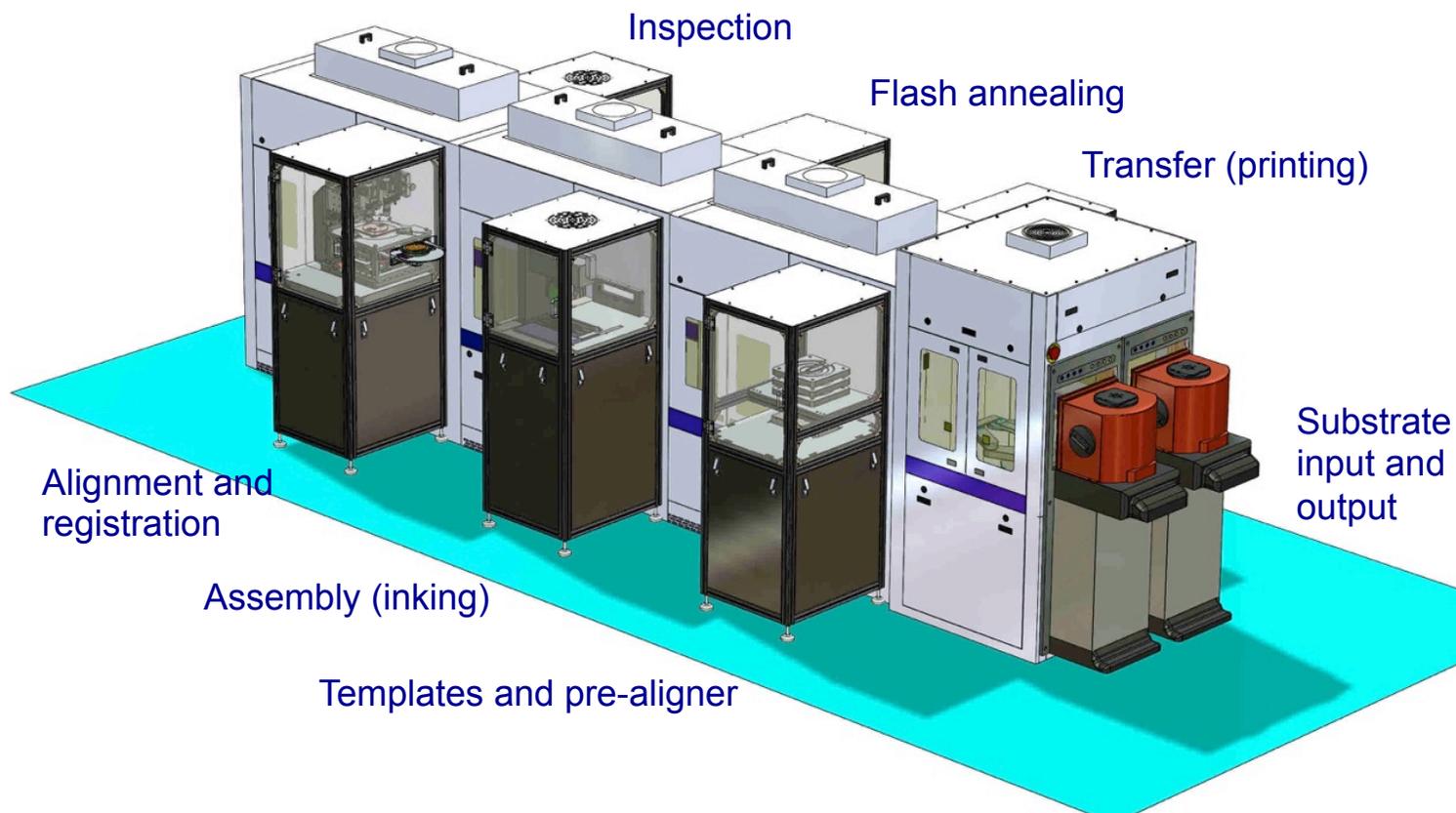


1. Core Nanoprinting Equipment
2. 35 patents
3. Core Experienced Team
4. Products:
  - Electronics (power or consumer electronics)
  - Chemical Sensors,
  - BioSensors: Cancer, Antibiotics, Physical  
and Fitness Indicator
  - Display applications



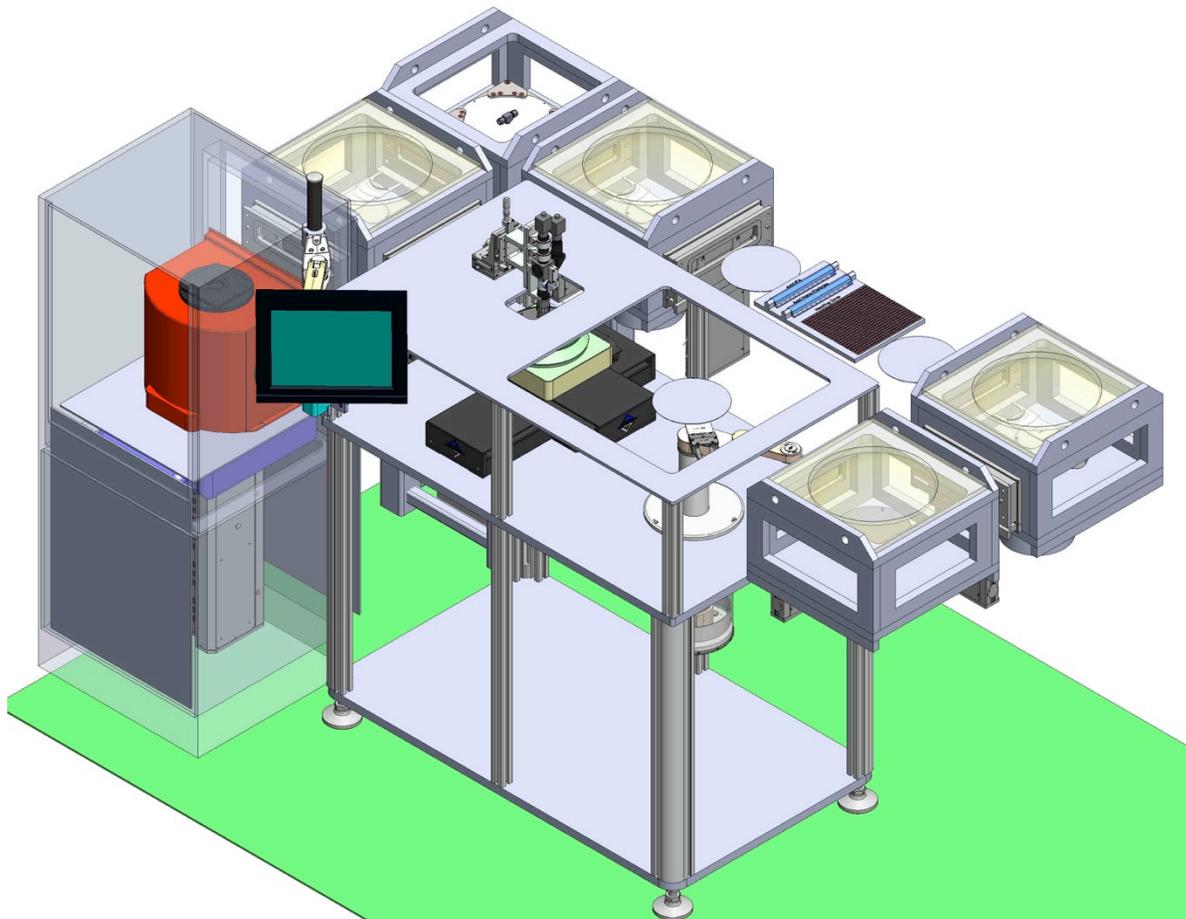
# Gen 2 NanoOPS Printing System

The second generation NanoOPS printing System, currently being built, has the ability to print nanoscale sensors and electronics on any polymer substrate. The system is fully automated with built-in alignment and registration, inspection and annealing.



# Gen 3 NanoOPS Printing System

Designing and Building the third generation NanoOPS printer that has the ability to print nano and microscale patterns and structures on any substrate (silicon, glass, ceramic, or metal) is underway.



# Summary

- Printing at the nanoscale introduces a disruptive technology for making nano and microelectronics that will change the electronics and sensor landscape.
- Printing nano and micro electronics costs 10 to 100 times less than conventional fabrication.
- 1000 times faster printing with a 1000 times smaller patterns than inkjet or 3D printing.
- Electronics are printed at ambient temperature and pressure, on any rigid or flexible substrate, using any conductive, semiconducting or insulating materials (organic or inorganic).
- Other benefits of printed electronics and sensors are: sustainable manufacturing, improved performance and the use of any existing and new nanomaterials, etc.
- This will open the door to many new and innovative applications.

**Thank you, 감사합니다**

**Questions and Discussion?**

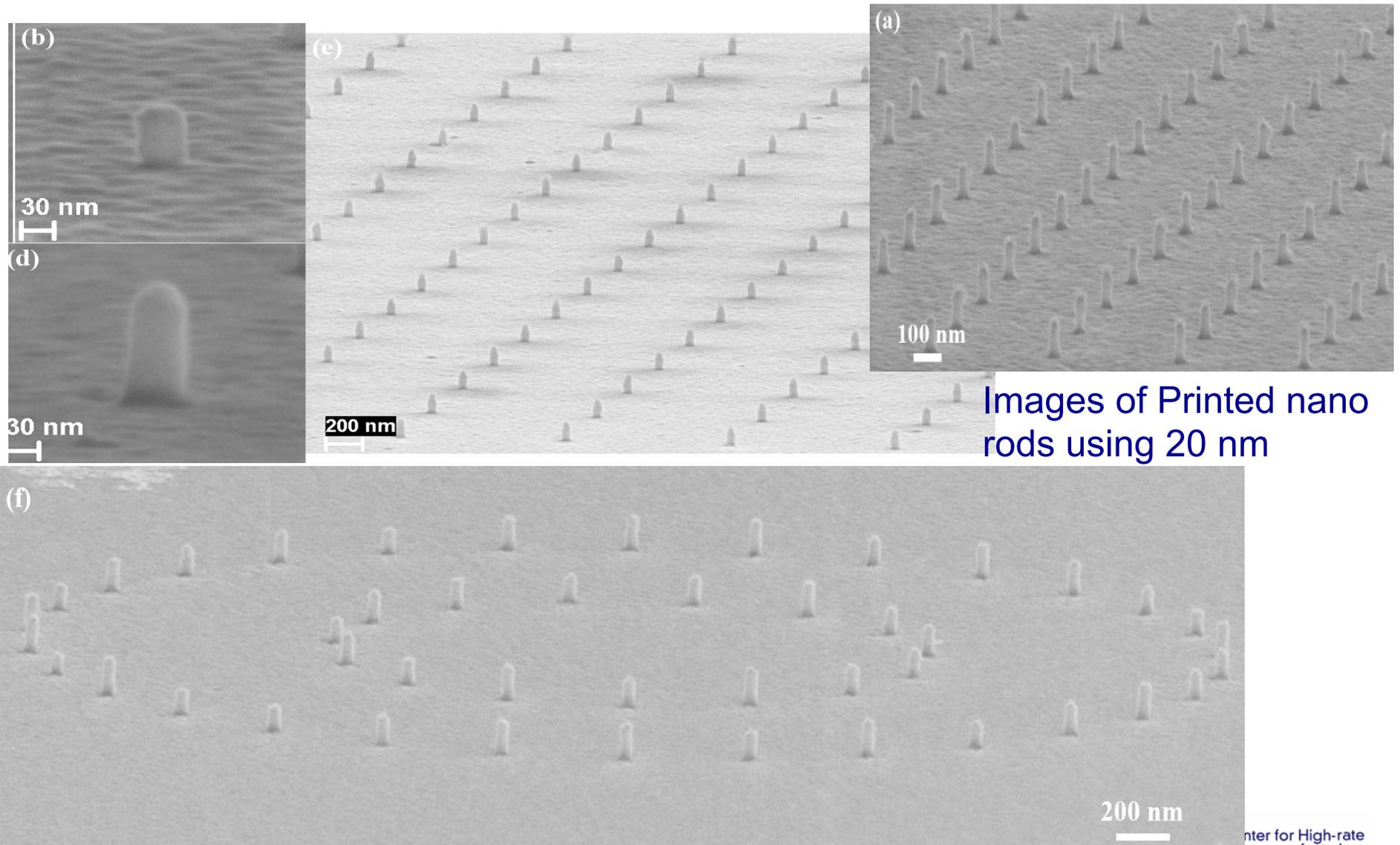
Prof. and Director Ahmed Busnaina  
Northeastern University

[a.busnaina@northeastern.edu](mailto:a.busnaina@northeastern.edu)

[www.northeastern.edu/nano](http://www.northeastern.edu/nano)

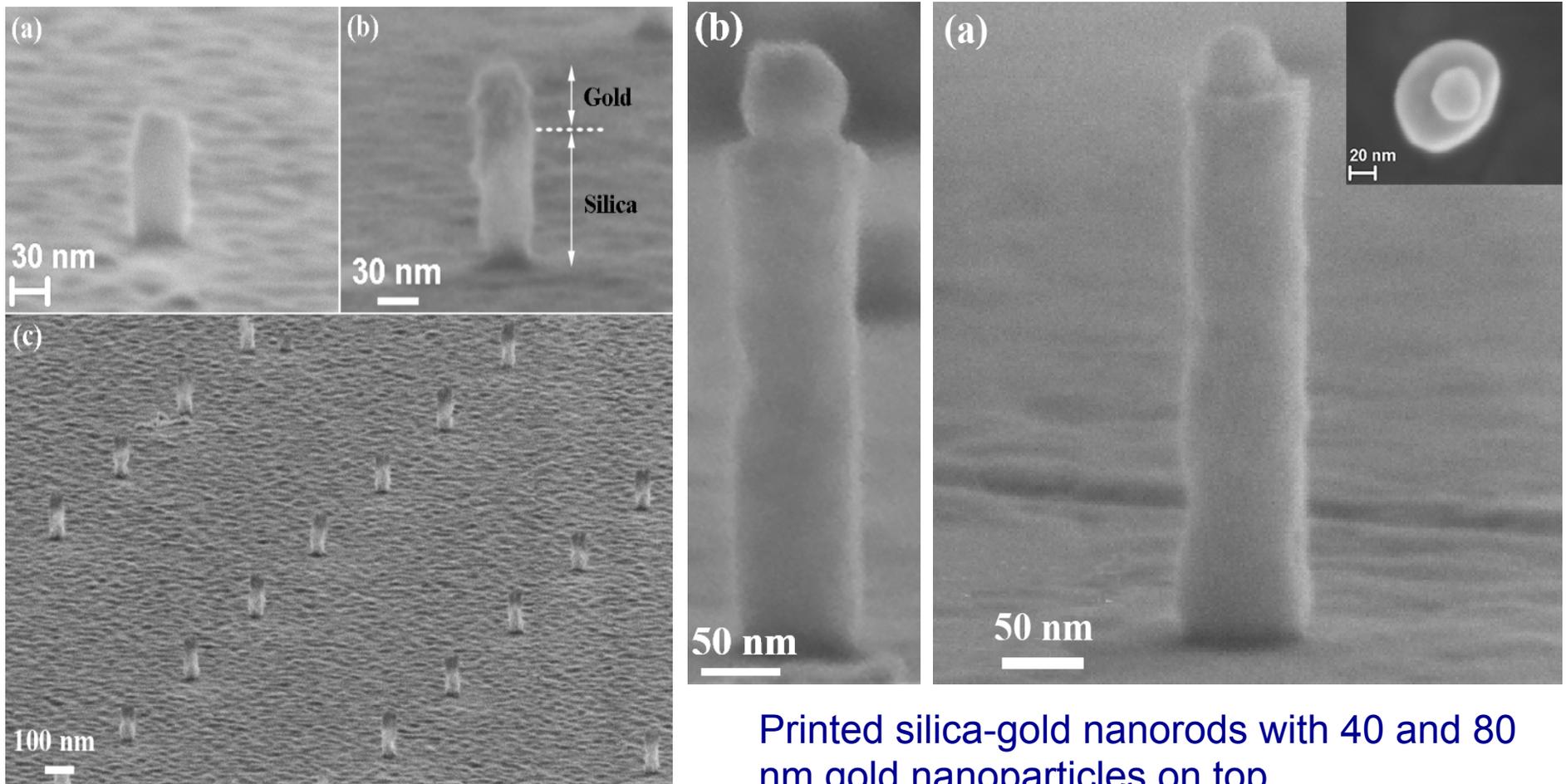
[www.nanomanufacturing.us](http://www.nanomanufacturing.us)

# Printing Nano Structures



Images of Printed nano rods using 20 nm

# What we can do with printing LEDs Structures

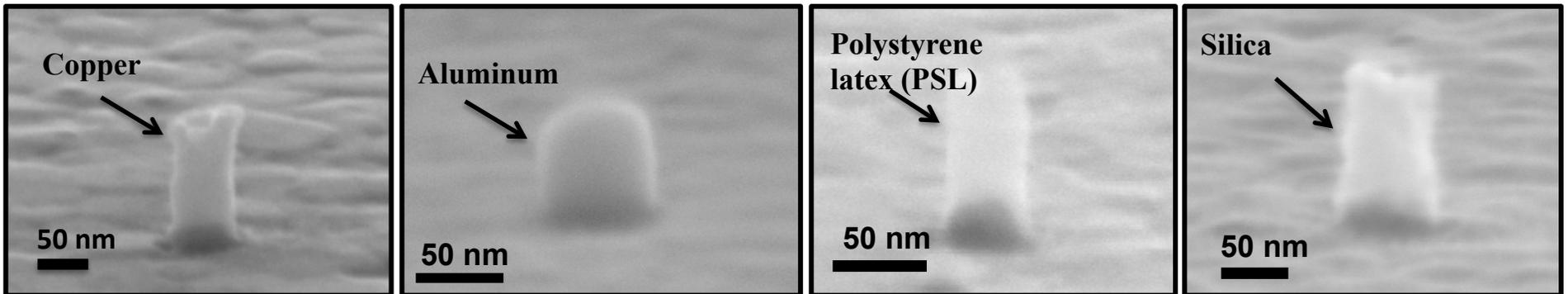


Printed hybrid silica-gold nano rods over a large area.

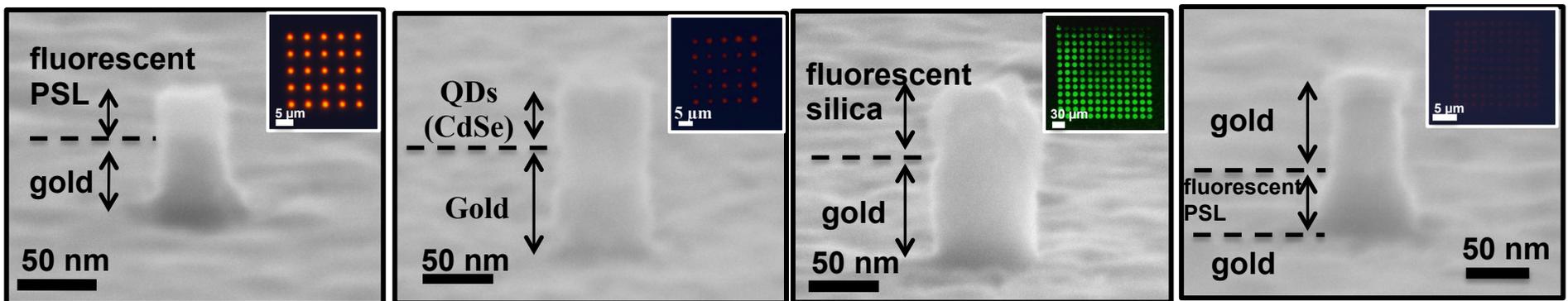
Printed silica-gold nanorods with 40 and 80 nm gold nanoparticles on top.

# What we can do with printing LEDs Structure

## *Homogenous nanopillars:*

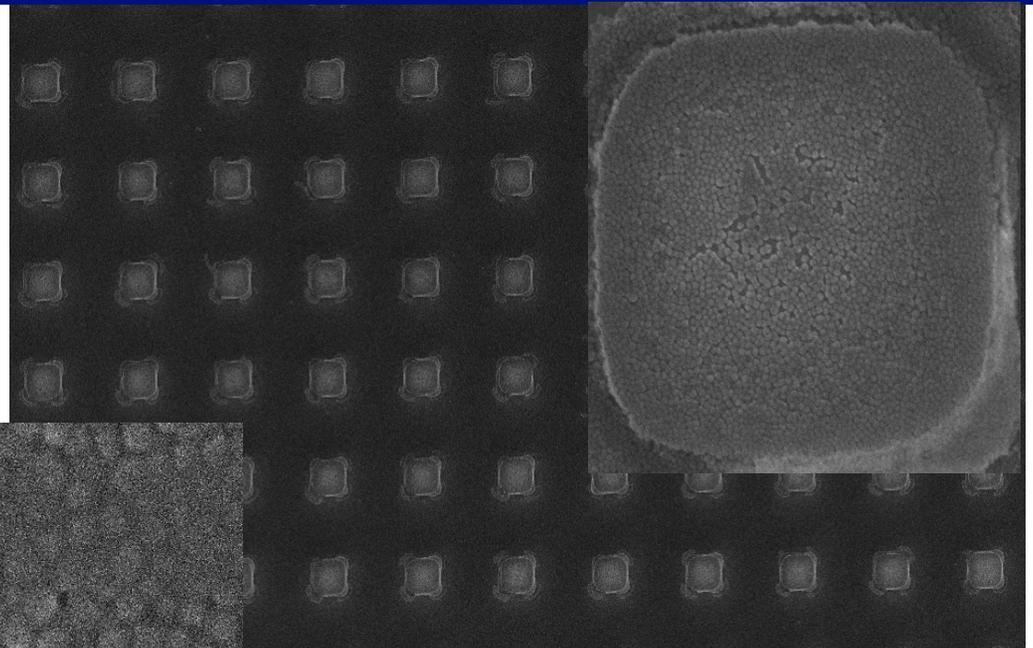


## *Hybrid nanopillars:*



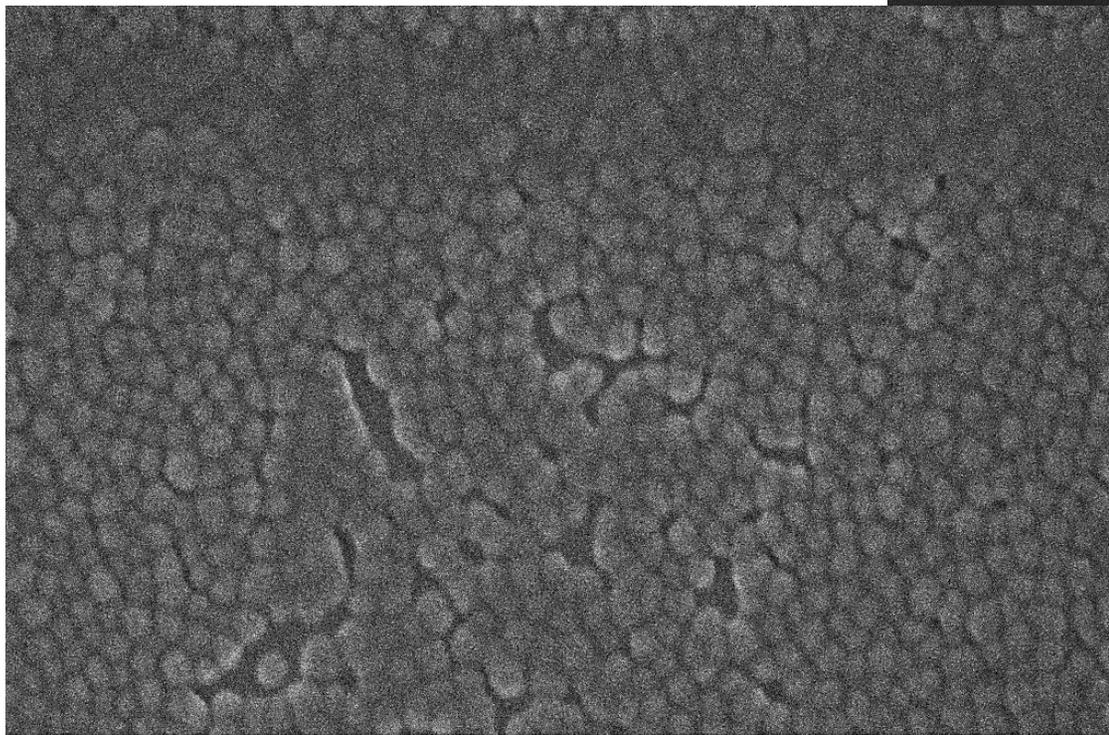
# What we can do with precise printing of QDs?

- Large scale printing of a single layer 20nm silica nano particles.



1  $\mu\text{m}^*$   
H  
Mag = 2.57 K X

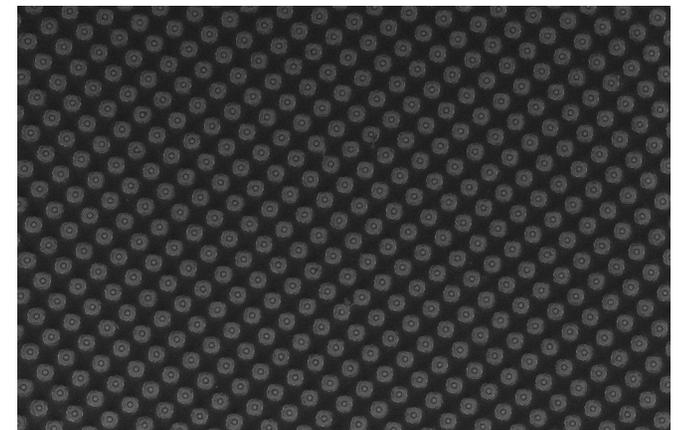
WD = 5.1 mm  
EHT = 10.00 kV  
Signal A = InLens



User Name = ABBASI  
Date :22 Aug 2017  
Time :18:07:19

100 nm\*  
Mag = 135.44 K X

WD = 5.1 mm  
EHT = 10.00 kV  
Signal A = InLens



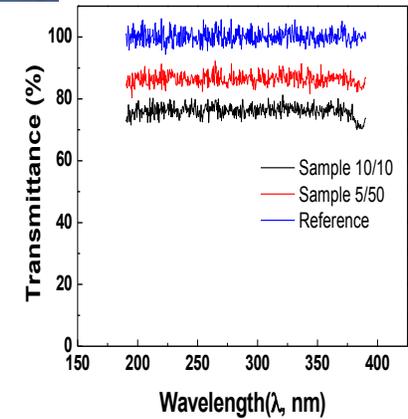
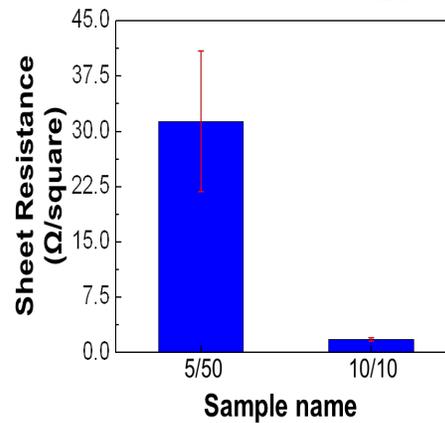
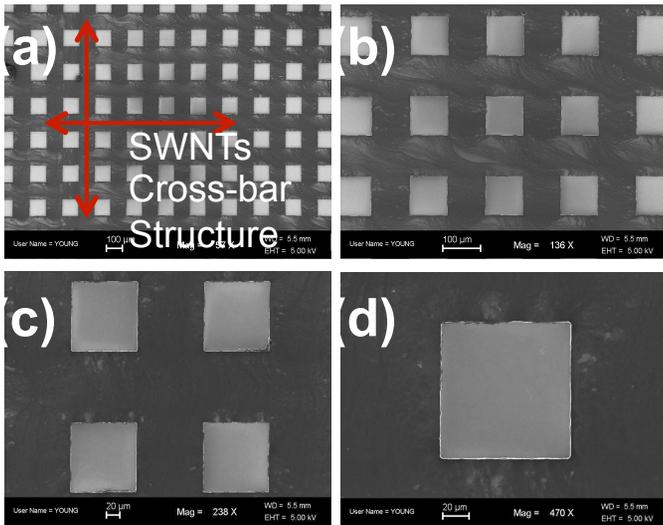
User Name = ABBASI  
Date :21 Aug 2017

10  $\mu\text{m}^*$

WD = 4.1 mm  
EHT = 10.00 kV

# Functional Materials and Surfaces

- **Ordered CNT materials for EMI shielding** → Excellent conductivity and transparency



- **Active camouflage** → Designed structures for very good absorption in the visible (red) and near infrared regime

